

SYNCHRONOUS DRAM

MT48LC8M16LFF4, MT48V8M16LFF4,
MT48LC8M16TG, MT48V8M16TG,
MT48V8M16P, MT48LC4M32LFF5,
MT48V4M32LFF5

Features

- Temperature Compensated Self Refresh (TCSR)
- Fully synchronous; all signals registered on positive edge of system clock
- Internal pipelined operation; column address can be changed every clock cycle
- Internal banks for hiding row access/precharge
- Programmable burst lengths: 1, 2, 4, 8, or full page
- Auto Precharge, includes CONCURRENT auto precharge, and Auto Refresh Modes
- Self Refresh Mode; standard and low power
- 64ms, 4,096-cycle refresh
- LVTTTL-compatible inputs and outputs
- Low voltage power supply
- Partial Array Self Refresh power-saving mode

Options

- VDD/VDDQ
3.3V/3.3V
2.5V/2.5V – 1.8V
- Configurations
8 Meg x 16 (2 Meg x 16 x 4 banks)
4 Meg x 32 (1 Meg x 32 x 4 banks)
- Package/Ball out
54-ball VFBCA (8mm x 8mm)¹
54-ball VFBCA (8mm x 8mm)¹ Lead-Free
90-ball VFBCA (8mm x 13mm)²
90-ball VFBCA (8mm x 13mm)² Lead-Free
54-Pin TSOP II (400 mil)
54-Pin TSOP II (400 mil) Lead-Free
- Timing (Cycle Time)
7.5ns @ CL = 3 (133 MHz)
8ns @ CL = 3 (125 MHz)
10ns @ CL = 3 (100 MHz)
- Temperature
Commercial (0°C to +70°C)
Industrial (-40°C to +85°C)
Extended (-25°C to +75°C)

Marking

LC
V
8M16
4M32
F4
B4
F5
B5
TG
P
-75M
-8
-10
None
IT
XT

Table 1: Configurations

	8 MEG X 16	4 MEG X 32
Configuration	2 Meg x 16 x 4 banks	1 Meg x 32 x 4 banks
Refresh Count	4K	4K
Row Addressing	4K (A0–A11)	4K (A0–A11)
Bank Addressing	4 (BA0, BA1)	4 (BA0, BA1)
Column Addressing	512 (A0–A8)	256 (A0–A7)

Table 2: Key Timing Parameters

CL = CAS (READ) latency

SPEED GRADE	CLOCK FREQUENCY	ACCESS TIME			t _{RCD}	t _{RP}
		CL = 1	CL = 2	CL = 3		
-75M	133MHz	-	-	5.4	19ns	19ns
-8	125 MHz	-	-	7ns	20ns	20ns
-10	100 MHz	-	-	7ns	20ns	20ns
-75M	100MHz	-	6	-	19ns	19ns
-8	100 MHz	-	8ns	-	20ns	20ns
-10	83 MHz	-	8ns	-	20ns	20ns
-8	50 MHz	19ns	-	-	20ns	20ns
-10	40 MHz	22ns	-	-	20ns	20ns

Part Number Example:

MT48V8M16LFB5-8

NOTE: 1. x16 only.
2. x32 only.

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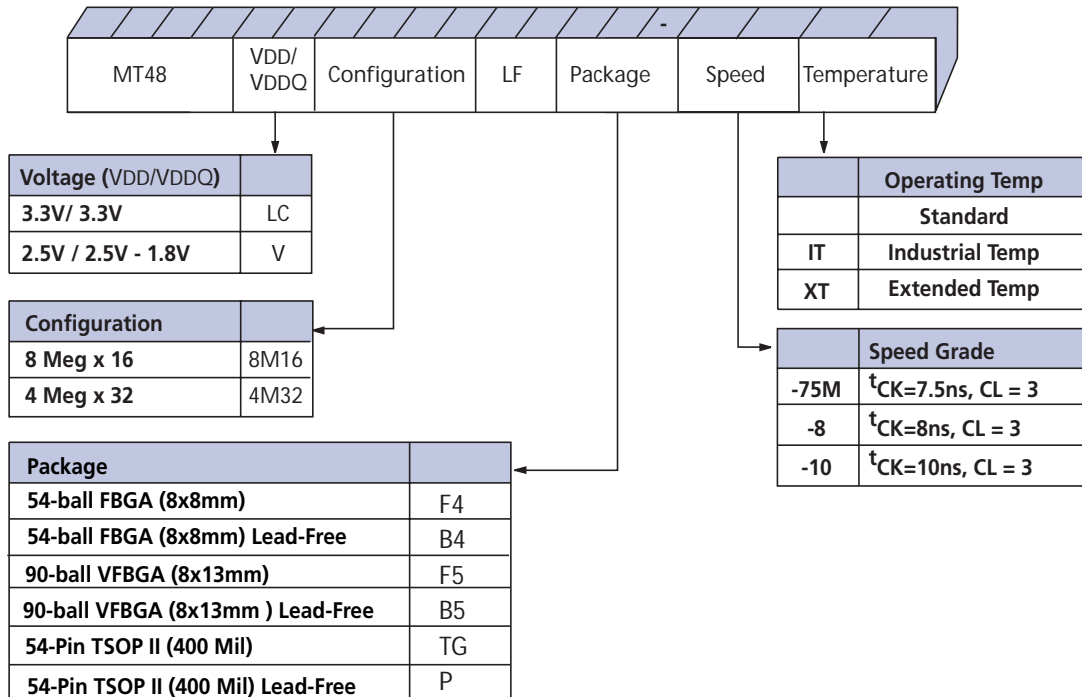
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Figure 4: 128Mb SDRAM Part Numbers

 Example Part Number: MT48V4M32LFF5-10XT


NOTE: Not all speeds and configurations are available.

FBGA Part Marking Decoder

Due to space limitations, FBGA-packaged components have an abbreviated part marking that is different from the part number. Micron's new FBGA Part Marking Decoder makes it easier to understand that part marking. Visit the web site at www.micron.com/decoder.

General Description

The Micron® 128Mb SDRAM is a high-speed CMOS, dynamic random-access memory containing 134,217,728 bits. It is internally configured as a quad-bank DRAM with a synchronous interface (all signals are registered on the positive edge of the clock signal, CLK). Each of the x16's 33,554,432-bit banks is organized as 4,096 rows by 512 columns by 16 bits. Each of the x32's 33,554,432-bit banks is organized as 4,096 rows by 256 columns by 32 bits.

Read and write accesses to the SDRAM are burst oriented; accesses start at a selected location and continue for a programmed number of locations in a programmed sequence. Accesses begin with the registration of an ACTIVE command, which is then fol-

lowed by a READ or WRITE command. The address bits registered coincident with the ACTIVE command are used to select the bank and row to be accessed (BA0, BA1 select the bank; A0-A11) select the row). The address bits registered coincident with the READ or WRITE command are used to select the starting column location for the burst access.

The SDRAM provides for programmable read or write burst lengths of 1, 2, 4, or 8 locations, or the full page, with a burst terminate option. An auto precharge function may be enabled to provide a self-timed row precharge that is initiated at the end of the burst sequence.

The 128Mb SDRAM uses an internal pipelined architecture to achieve high-speed operation. This architecture is compatible with the 2n rule of prefetch architectures, but it also allows the column address to be changed on every clock cycle to achieve a high-speed, fully random access. Precharging one bank while accessing one of the other three banks will hide the precharge cycles and provide seamless high-speed, random-access operation.

The 128Mb SDRAM is designed to operate in 3.3V or 2.5V low-power memory systems. The 2.5V version is compatible with 1.8V I/O interface. An auto refresh

Figure 6: Functional Block Diagram 4 Meg x 32 SDRAM

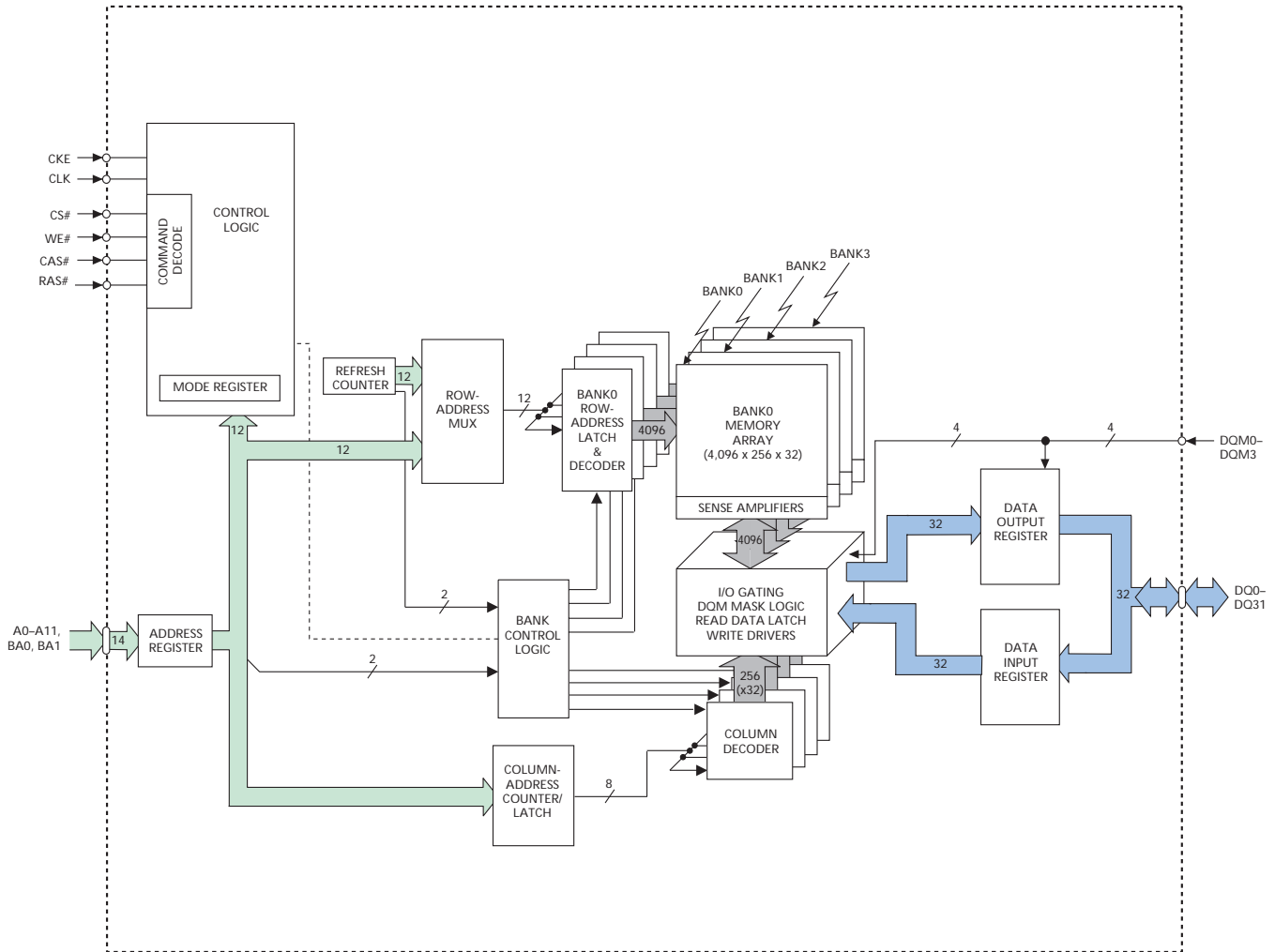


Table 3: Ball Descriptions: 54-Ball VFBGA

54-BALL VFBGA	SYMBOL	TYPE	DESCRIPTION
F2	CLK	Input	Clock: CLK is driven by the system clock. All SDRAM input signals are sampled on the positive edge of CLK. CLK also increments the internal burst counter and controls the output registers.
F3	CKE	Input	Clock Enable: CKE activates (HIGH) and deactivates (LOW) the CLK signal. Deactivating the clock provides PRECHARGE POWER-DOWN and SELF REFRESH operation (all banks idle), ACTIVE POWER-DOWN (row active in any bank) or CLOCK SUSPEND operation (burst/access in progress). CKE is synchronous except after the device enters power-down and self refresh modes, where CKE becomes asynchronous until after exiting the same mode. The input buffers, including CLK, are disabled during power-down and self refresh modes, providing low standby power. CKE may be tied HIGH.
G9	CS#	Input	Chip Select: CS# enables (registered LOW) and disables (registered HIGH) the command decoder. All commands are masked when CS# is registered HIGH. CS# provides for external bank selection on systems with multiple banks. CS# is considered part of the command code.
F7, F8, F9	CAS#, RAS#, WE#	Input	Command Inputs: CAS#, RAS#, and WE# (along with CS#) define the command being entered.
E8, F1	LDQM, UDQM	Input	Input/Output Mask: DQM is sampled HIGH and is an input mask signal for write accesses and an output enable signal for read accesses. Input data is masked during a WRITE cycle. The output buffers are placed in a High-Z state (two-clock latency) when during a READ cycle. LDQM corresponds to DQ0–DQ7, UDQM corresponds to DQ8–DQ15. LDQM and UDQM are considered same state when referenced as DQM.
G7, G8	BA0, BA1	Input	Bank Address Input(s): BA0 and BA1 define to which bank the ACTIVE, READ, WRITE or PRECHARGE command is being applied. These pins also provide the op-code during a LOAD MODE REGISTER command
H7, H8, J8, J7, J3, J2, H3, H2, H1, G3, H9, G2	A0–A6 A7–A11	Input	Address Inputs: A0–A11 are sampled during the ACTIVE command (row-address A0–A11) and READ/WRITE command (column-address A0–A8; with A10 defining auto precharge) to select one location out of the memory array in the respective bank. A10 is sampled during a PRECHARGE command to determine if all banks are to be precharged (A10 HIGH) or bank selected by BA0, BA1 (LOW). The address inputs also provide the op-code during a LOAD MODE REGISTER command.
A8, B9, B8, C9, C8, D9, D8, E9, E1, D2, D1, C2, C1, B2, B1, A2	DQ0–DQ5 DQ6–DQ11 DQ12–DQ15	I/O	Data Input/Output: Data bus
E2, G1	NC	–	No Connect: These pins should be left unconnected. G1 is a no connect for this part but may be used as A12 in future designs.
A7, B3, C7, D3	V _{DDQ}	Supply	DQ Power: Isolated DQ power on the die to improve noise immunity.
A3, B7, C3, D7,	V _{SSQ}	Supply	DQ Ground: Isolated DQ power on the die to improve noise immunity.
A9, E7, J9	V _{DD}	Supply	Power Supply: Voltage dependant on option.
A1, E3, J1	V _{SS}	Supply	Ground.

Table 4: Ball Descriptions: 90-Ball VFBGA

90-BALL FBGA	SYMBOL	TYPE	DESCRIPTION
J1	CLK	Input	Clock: CLK is driven by the system clock. All SDRAM input signals are sampled on the positive edge of CLK. CLK also increments the internal burst counter and controls the output registers.
J2	CKE	Input	Clock Enable: CKE activates (HIGH) and deactivates (LOW) the CLK signal. Deactivating the clock provides PRECHARGE POWER-DOWN and SELF REFRESH operation (all banks idle), ACTIVE POWER-DOWN (row active in any bank) or CLOCK SUSPEND operation (burst/access in progress). CKE is synchronous except after the device enters power-down and self refresh modes, where CKE becomes asynchronous until after exiting the same mode. The input buffers, including CLK, are disabled during power-down and self refresh modes, providing low standby power. CKE may be tied HIGH.
J8	CS#	Input	Chip Select: CS# enables (registered LOW) and disables (registered HIGH) the command decoder. All commands are masked when CS# is registered HIGH. CS# provides for external bank selection on systems with multiple banks. CS# is considered part of the command code.
J9, K7, K8	RAS#, CAS#, WE#	Input	Command Inputs: RAS#, CAS#, and WE# (along with CS#) define the command being entered.
K9, K1, F8, F2	DQM0-3	Input	Input/Output Mask: DQM is sampled HIGH and is an input mask signal for write accesses and an output enable signal for read accesses. Input data is masked during a WRITE cycle. The output buffers are placed in a High-Z state (two-clock latency) when during a READ cycle. DQM0 corresponds to DQ0-DQ7, DQM1 corresponds to DQ8-DQ15, DQM2 corresponds to DQ16-DQ23 and DQM3 corresponds to DQ24-DQ31. DQM0-3 are considered same state when referenced as DQM.
J7, H8	BA0, BA1	Input	Bank Address Input(s): BA0 and BA1 define to which bank the ACTIVE, READ, WRITE or PRECHARGE command is being applied. These pins also provide the op-code during a LOAD MODE REGISTER command
G8, G9, F7, F3, G1, G2, G3, H1, H2, J3, G7, H9	A0-A5 A6-A11	Input	Address Inputs: A0-A11 are sampled during the ACTIVE command (row-address A0-A11) and READ/WRITE command (column-address A0-A7; with A10 defining auto precharge) to select one location out of the memory array in the respective bank. A10 is sampled during a PRECHARGE command to determine if all banks are to be precharged (A10 HIGH) or bank selected by BA0, BA1 (LOW). The address inputs also provide the op-code during a LOAD MODE REGISTER command.
R8, N7, R9, N8, P9, M8, M7, L8, L2, M3, M2, P1, N2, R1, N3, R2, E8, D7, D8, B9, C8, A9, C7, A8, A2, C3, A1, C2, B1, D2, D3, E2	DQ0-DQ5 DQ6-DQ11 DQ12-DQ17 DQ18-DQ23 DQ24-DQ29 DQ30-DQ31	I/O	Data Input/Output: Data bus
E3, E7, H3, H7, K2, K3	NC	-	No Connect: These pins should be left unconnected. H3 is a no connect for this part but may be used as A12 in future designs.
B2, B7, C9, D9, E1, L1, M9, N9, P2, P7	VDDQ	Supply	DQ Power: Isolated DQ power on the die to improve noise immunity.
B8, B3, C1, D1, E9, L9, M1, N1, P3, P8	VSSQ	Supply	DQ Ground: Isolated DQ power on the die to improve noise immunity.
A7, F9, L7, R7	VDD	Supply	Power Supply: Voltage dependant on option.
A3, F1, L3, R3	VSS	Supply	Ground.

Table 5: Pin Descriptions: 54-Pin TSOP (x16 Only)

TSOP PIN NUMBER	SYMBOL	TYPE	DESCRIPTION
38	CLK	Input	Clock: CLK is driven by the system clock. All SDRAM input signals are sampled on the positive edge of CLK. CLK also increments the internal burst counter and controls the output registers.
37	CKE	Input	Clock Enable: CKE activates (HIGH) and deactivates (LOW) the CLK signal. Deactivating the clock provides PRECHARGE POWER-DOWN and SELF REFRESH operation (all banks idle), ACTIVE POWER-DOWN (row active in any bank) or CLOCK SUSPEND operation (burst/access in progress). CKE is synchronous except after the device enters power-down and self refresh modes, where CKE becomes asynchronous until after exiting the same mode. The input buffers, including CLK, are disabled during power-down and self refresh modes, providing low standby power. CKE may be tied HIGH.
19	CS#	Input	Chip Select: CS# enables (registered LOW) and disables (registered HIGH) the command decoder. All commands are masked when CS# is registered HIGH. CS# provides for external bank selection on systems with multiple banks. CS# is considered part of the command code.
16, 17, 18	WE#, CAS#, RAS#	Input	Command Inputs: WE#, CAS#, and RAS# (along with CS#) define the command being entered.
15, 39	DQML, DQMH	Input	Input/Output Mask: DQM is sampled HIGH and is an input mask signal for write accesses and an output enable signal for read accesses. Input data is masked during a WRITE cycle. The output buffers are placed in a High-Z state (two-clock latency) when during a READ cycle. DQM0 corresponds to DQ0–DQ7, DQM1 corresponds to DQ8–DQ15, DQM2 corresponds to DQ16–DQ23 and DQM3 corresponds to DQ24–DQ31. LDQM corresponds to DQ0–DQ7, UDQM corresponds to DQ8–DQ15. LDQM and UDQM are considered same state when referenced as DQM.
20, 21	BA0, BA1	Input	Bank Address Input(s): BA0 and BA1 define to which bank the ACTIVE, READ, WRITE or PRECHARGE command is being applied. These pins also provide the op-code during a LOAD MODE REGISTER command
23, 24, 25, 29, 30, 31, 32, 33, 34, 22, 35	A0–A5 A6–A11	Input	Address Inputs: A0–A11 are sampled during the ACTIVE command (row-address A0–A11) and READ/WRITE command (column-address A0–A7; with A10 defining auto precharge) to select one location out of the memory array in the respective bank. A10 is sampled during a PRECHARGE command to determine if all banks are to be precharged (A10 HIGH) or bank selected by BA0, BA1 (LOW). The address inputs also provide the op-code during a LOAD MODE REGISTER command.
2, 4, 5, 7, 8, 10, 11, 13, 42, 49, 45, 47, 48, 50, 51	DQ0–DQ7 DQ8–DQ15	I/O	Data Input/Output: Data bus (x16 Only)
36, 40	NC	–	No Connect: These pins should be left unconnected. Pin 36 is a no connect for this part but may be used as A12 in future designs.
3, 9, 43, 49	V _{DDQ}	Supply	DQ Power: Isolated DQ power on the die to improve noise immunity.
6, 12, 46, 52	V _{SSQ}	Supply	DQ Ground: Isolated DQ power on the die to improve noise immunity.
1, 14, 27	V _{DD}	Supply	Power Supply: Voltage dependant on option.
28, 41, 54	V _{SS}	Supply	Ground.

Functional Description

In general, the 128Mb SDRAMs (2 Meg x16 x 4 banks and 1 Meg x 32 x 4 banks) are quad-bank DRAMs that operate at 3.3V or 2.5V and include a synchronous interface (all signals are registered on the positive edge of the clock signal, CLK). Each of the x16's 33,554,432-bit banks is organized as 4,096 rows by 512 columns by 16 bits. Each of the x32's 33,554,432-bit banks is organized as 4,096 rows by 256 columns by 32bits.

Read and write accesses to the SDRAM are burst oriented; accesses start at a selected location and continue for a programmed number of locations in a programmed sequence. Accesses begin with the registration of an ACTIVE command, which is then followed by a READ or WRITE command. The address bits registered coincident with the ACTIVE command are used to select the bank and row to be accessed (BA0 and BA1 select the bank, A0-A11 select the row). The address bits (x16: A0-A8; x32: A0-A7) registered coincident with the READ or WRITE command are used to select the starting column location for the burst access.

Prior to normal operation, the SDRAM must be initialized. The following sections provide detailed information covering device initialization, register definition, command descriptions and device operation.

Initialization

SDRAMs must be powered up and initialized in a predefined manner. Operational procedures other than those specified may result in undefined operation. Once power is applied to Vdd and VddQ (simultaneously) and the clock is stable (stable clock is defined as a signal cycling within timing constraints specified for the clock pin), the SDRAM requires a 100µs delay prior to issuing any command other than a COMMAND INHIBIT or NOP. Starting at some point during this 100µs period and continuing at least through the end of this period, Command Inhibit or NOP commands should be applied.

Once the 100µs delay has been satisfied with at least one Command Inhibit or NOP command having been applied, a PRECHARGE command should be applied. All banks must then be precharged, thereby placing the device in the all banks idle state.

Once in the idle state, two AUTO refresh cycles must be performed. After the AUTO refresh cycles are complete, the SDRAM is ready for mode register programming. Because the mode register will power up in an unknown state, it should be loaded prior to applying any operational command.

Register Definition

Mode Register

In order to achieve low power consumption, there are two mode registers in the Mobile component, Mode Register and Extended Mode Register. For this section, Mode Register is referred to. Extended Mode register is discussed on 15. The mode register is used to define the specific mode of operation of the SDRAM. This definition includes the selection of a burst length, a burst type, a CAS latency, an operating mode and a write burst mode, as shown in Figure 7. The mode register is programmed via the LOAD MODE REGISTER command and will retain the stored information until it is programmed again or the device loses power.

Mode Register bits M0-M2 specify the burst length, M3 specifies the type of burst (sequential or interleaved), M4-M6 specify the CAS latency, M7 and M8 specify the operating mode, M9 specify the Write Burst mode (single or programmed burst length), M10, and M11 are reserved and must be set to zero. To address the mode register M12 and M13 must be set to zero.

The mode register must be loaded when all banks are idle, and the controller must wait the specified time before initiating the subsequent operation. Violating either of these requirements will result in unspecified operation.

Burst Length

Read and write accesses to the SDRAM are burst oriented, with the burst length being programmable, as shown in Figure 8 on page 14. The burst length determines the maximum number of column locations that can be accessed for a given READ or WRITE command. Burst lengths of 1, 2, 4, or 8 locations are available for both the sequential and the interleaved burst types, and a full-page burst is available for the sequential type. The full-page burst is used in conjunction with the BURST TERMINATE command to generate arbitrary burst lengths. If a full page burst is not terminated at the end of the page it could wrap to column zero and continue.

Reserved states should not be used, as unknown operation or incompatibility with future versions may result.

When a READ or WRITE command is issued, a block of columns equal to the burst length is effectively selected. All accesses for that burst take place within this block, meaning that the burst will wrap within the block if a boundary is reached. The block is uniquely selected by A1-A8 (x16) or A1-A7 (x32) when the burst

length is set to two; by A2-A8 (x16) or A2-A7 (x32) when the burst length is set to four; and by A3-A8 (x16) or A3-A7 (x32) when the burst length is set to eight. The remaining (least significant) address bit(s) is (are) used to select the starting location within the block. Full-page bursts wrap within the page if the boundary is reached.

Burst Type

Accesses within a given burst may be programmed to be either sequential or interleaved; this is referred to as the burst type and is selected via bit M3. Note only a sequential burst is allowed for full page bursts.

The ordering of accesses within a burst is determined by the burst length, the burst type and the starting column address, as shown in Table 6 on page 14.

Figure 7: Mode Register Definition

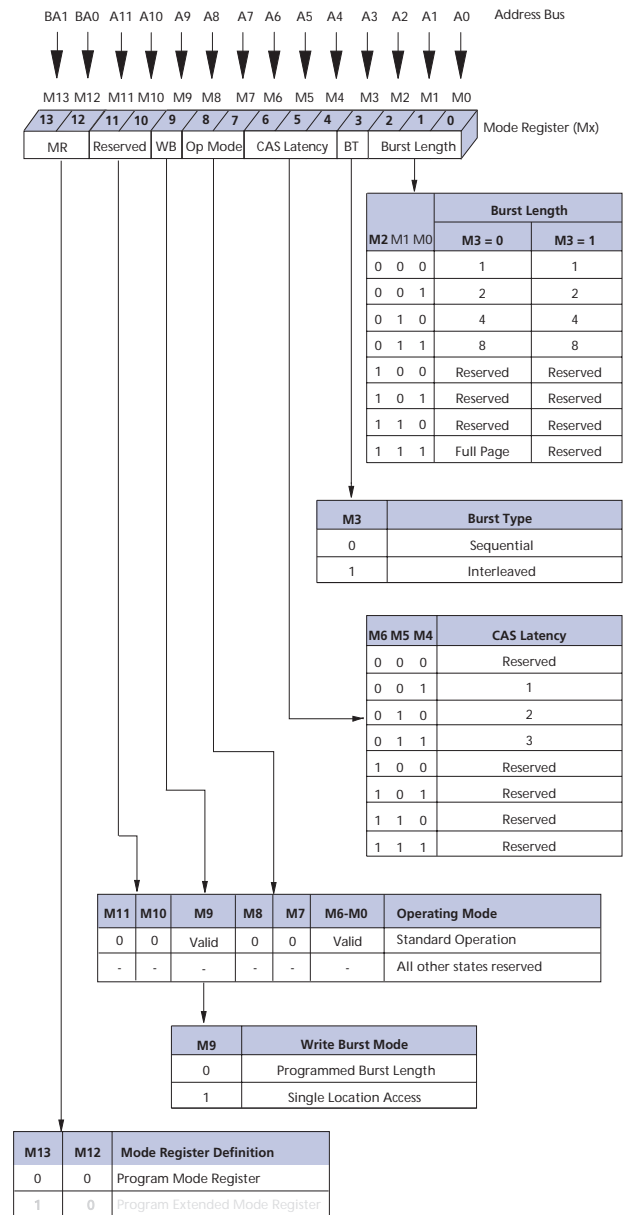


Table 6: Burst Definition

BURST LENGTH	STARTING COLUMN ADDRESS			ORDER OF ACCESSES WITHIN A BURST	
				TYPE = SEQUENTIAL	TYPE = INTERLEAVED
2			A0		
			0	0-1	0-1
			1	1-0	1-0
4		A1	A0		
		0	0	0-1-2-3	0-1-2-3
		0	1	1-2-3-0	1-0-3-2
		1	0	2-3-0-1	2-3-0-1
		1	1	3-0-1-2	3-2-1-0
8	A2	A1	A0		
	0	0	0	0-1-2-3-4-5-6-7	0-1-2-3-4-5-6-7
	0	0	1	1-2-3-4-5-6-7-0	1-0-3-2-5-4-7-6
	0	1	0	2-3-4-5-6-7-0-1	2-3-0-1-6-7-4-5
	0	1	1	3-4-5-6-7-0-1-2	3-2-1-0-7-6-5-4
	1	0	0	4-5-6-7-0-1-2-3	4-5-6-7-0-1-2-3
	1	0	1	5-6-7-0-1-2-3-4	5-4-7-6-1-0-3-2
	1	1	0	6-7-0-1-2-3-4-5	6-7-4-5-2-3-0-1
	1	1	1	7-0-1-2-3-4-5-6	7-6-5-4-3-2-1-0
Full Page (y)	n = A0-A8 for x16, A0-A7 for x32 (location 0-y)			Cn, Cn + 1, Cn + 2, Cn + 3, Cn + 4... ...Cn - 1, Cn...	Not Supported

NOTE:

- For full-page accesses: $y = 512$ (x16), $y = 256$ (x32).
- For a burst length of two, A1-A8 (x16) or A1-A7 (x32) select the block-of-two burst; A0 selects the starting column within the block.
- For a burst length of four, A2-A8 (x16) or A2-A7 (x32) select the block-of-four burst; A0-A1 select the starting column within the block.
- For a burst length of eight, A3-A8 (x16) or A3-A7 (x32) select the block-of-eight burst; A0-A2 select the starting column within the block.
- For a full-page burst, the full row is selected and A0-A8 (x16) or A0-A7 (x32) select the starting column.
- Whenever a boundary of the block is reached within a given sequence above, the following access wraps within the block.
- For a burst length of one, A0-A8 (x16) or A0-A7 (x32) select the unique column to be accessed, and mode register bit M3 is ignored.

CAS Latency

The CAS latency is the delay, in clock cycles, between the registration of a READ command and the availability of the first piece of output data. The latency can be set to one, two, or three clocks.

If a READ command is registered at clock edge n , and the latency is m clocks, the data will be available by clock edge $n + m$. The DQs will start driving as a result of the clock edge one cycle earlier ($n + m - 1$), and provided that the relevant access times are met, the data will be valid by clock edge $n + m$. For example, assuming that the clock cycle time is such that all relevant access times are met, if a read command is registered at T0 and the latency is programmed to two clocks, the DQs will start driving after T1 and the data will be valid by T2, as shown in Figure 8. Table 7 indicates the operating frequencies at which each CAS latency setting can be used.

Reserved states should not be used as unknown operation or incompatibility with future versions may result.

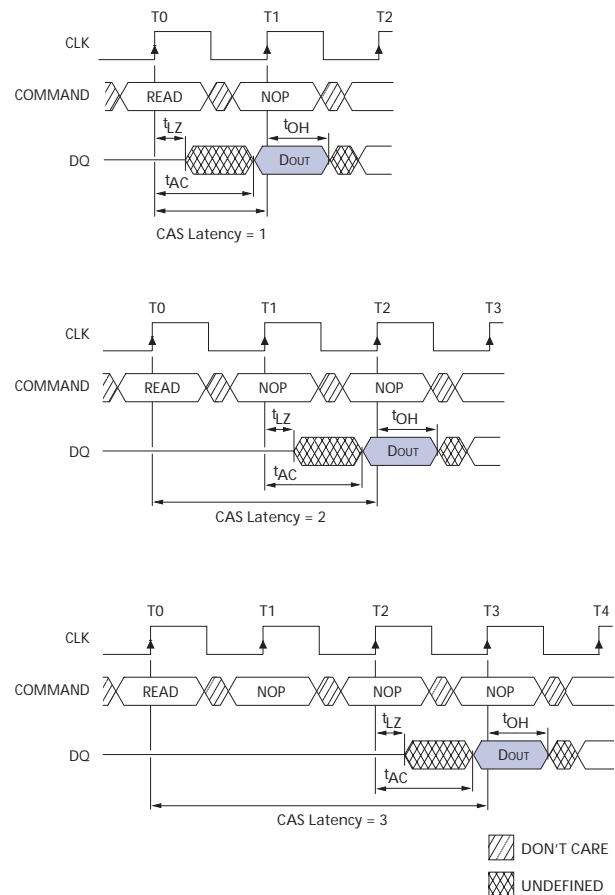
Figure 8: CAS Latency


Table 7: CAS Latency

SPEED	ALLOWABLE OPERATING FREQUENCY (MHZ)		
	CAS LATENCY = 1	CAS LATENCY = 2	CAS LATENCY = 3
-75M	-	≤ 100	≤ 133
- 8	≤ 50	≤ 100	≤ 125
- 10	≤ 40	≤ 83	≤ 100

Write Burst Mode

When M9=0, the burst length programmed into M0-M2 applies to both READ and WRITE burst. If M9 = 1, all WRITE bursts will only be single location access regardless of the burst length setting in the mode register. READ burst lengths are unaffected by the state of M9.

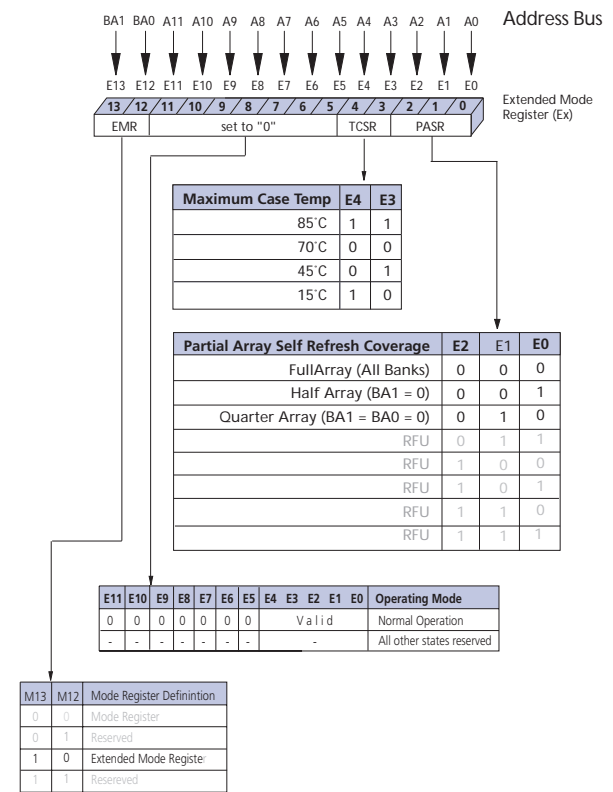
Operating Mode

The normal operating mode is selected by setting M7, M8, M10 and M11 to zero; all the other combinations of values for M7, M8, M10 and M11 are reserved for future use and/or test modes.

Test modes and reserved states should not be used because unknown operation or incompatibility with future versions may result.

Extended Mode Register

The Extended Mode Register controls the functions beyond those controlled by the Mode Register. These additional functions are special features of the Mobile device. They include Temperature Compensated Self Refresh Control (TCSR), and Partial Array Self Refresh (PASR).

Figure 9: Extended Mode Register


Notes: 1. M13 and M12 (BA1 and BA0) must be "1, 0" to select the Extended Mode Register (vs. the base Mode Register).
2. RFU: Reserved for Future Use

The Extended Mode Register is programmed via the Mode Register Set command (BA1=1,BA0=0) and retains the stored information until it is programmed again or the device loses power.

The Extended Mode Register must be programmed with E5 through E11 set to "0". The Extended Mode Register must be loaded when all banks are idle and no bursts are in progress, and the controller must wait the specified time before initiating any subsequent operation. Violating either of these requirements results in unspecified operation. The Extended Mode Register must be programmed in order to ensure proper operation.

Temperature Compensated Self Refresh

Temperature Compensated Self Refresh (TCSR) allows the controller to program the Refresh interval during SELF REFRESH mode, according to the case temperature of the Mobile device. This allows great power savings during SELF REFRESH during most operating temperature ranges. Only during extreme

temperatures would the controller have to select a higher TCSR level that will guarantee data during SELF REFRESH.

Every cell in the DRAM requires refreshing due to the capacitor losing its charge over time. The refresh rate is dependent on temperature. At higher temperatures a capacitor loses charge quicker than at lower temperatures, requiring the cells to be refreshed more often. Historically, during Self Refresh, the refresh rate has been set to accommodate the worst case, or highest temperature range expected.

Thus, during ambient temperatures, the power consumed during refresh was unnecessarily high, because the refresh rate was set to accommodate the higher temperatures. Setting E4 and E3, allows the DRAM to accommodate more specific temperature regions during SELF REFRESH. There are four temperature settings, which will vary the SELF REFRESH current

according to the selected temperature. This selectable refresh rate will save power when the DRAM is operating at normal temperatures.

Partial Array Self Refresh

For further power savings during SELF REFRESH, the Partial Array Self Refresh (PASR) feature allows the controller to select the amount of memory that will be refreshed during SELF REFRESH. The refresh options are all banks (banks 0, 1, 2, and 3); two banks (banks 0 and 1); and one bank (bank 0). WRITE and READ commands occur to any bank selected during standard operation, but only the selected banks in PASR will be refreshed during SELF REFRESH. It's important to note that data in banks 2 and 3 will be lost when the two bank option is used. Data will be lost in banks 1, 2, and 3 when the one bank option is used.

Commands

Truth Table 1 provides a quick reference of available commands. This is followed by a written description of each command. Three additional Truth Tables appear

following the Operation section; these tables provide current state/next state information.

Table 8: Truth Table–Commands and DQM Operation

(Note: 1)

NAME (FUNCTION)	CS#	RAS#	CAS#	WE#	DQM	ADDR	DQS	NOTES
COMMAND INHIBIT (NOP)	H	X	X	X	X	X	X	
NO OPERATION (NOP)	L	H	H	H	X	X	X	
ACTIVE (Select bank and activate row)	L	L	H	H	X	Bank/Row	X	3
READ (Select bank and column, and start READ burst)	L	H	L	H	L/H ⁸	Bank/Col	X	4
WRITE (Select bank and column, and start WRITE burst)	L	H	L	L	L/H ⁸	Bank/Col	Valid	4
BURST TERMINATE	L	H	H	L	X	X	Active	
PRECHARGE (Deactivate row in bank or banks)	L	L	H	L	X	Code	X	5
AUTO REFRESH or SELF REFRESH (Enter self refresh mode)	L	L	L	H	X	X	X	6, 7
LOAD MODE REGISTER	L	L	L	L	X	Op-Code	X	2
Write Enable/Output Enable	–	–	–	–	L	–	Active	8
Write Inhibit/Output High-Z	–	–	–	–	H	–	High-Z	8

NOTE:

1. CKE is HIGH for all commands shown except SELF REFRESH.
2. A0-A10 define the op-code written to the mode register. BA0-BA1 select either the mode register or the extended mode register (BA0=BA1=0 select the mode register, BA1=1, BA0=0 selects the extended mode register, all other combinations of BA0-BA1 are reserved.)
3. A0-A11 provide row address, and BA0, BA1 determine which bank is made active.
4. A0-A8 (x16) or A0-A7 (x32) provide column address; A10 HIGH enables the auto precharge feature (nonpersistent), while A10 LOW disables the auto precharge feature; BA0, BA1 determine which bank is being read from or written to.
5. A10 LOW: BA0, BA1 determine the bank being precharged. A10 HIGH: All banks precharged and BA0, BA1 are "Don't Care."
6. This command is AUTO REFRESH if CKE is HIGH, SELF REFRESH if CKE is LOW.
7. Internal refresh counter controls row addressing; all inputs and I/Os are "Don't Care" except for CKE.
8. Activates or deactivates the DQs during WRITES (zero-clock delay) and READs (two-clock delay). For x16: LDQM controls DQ0-DQ7 and UDQM controls DQ8-DQ15. For x32: DQM0 controls DQ0-7, DQM1 controls DQ8-15, DQM2 controls DQ16-23, and DQM3 controls DQ24-31.

Command Inhibit

The COMMAND INHIBIT function prevents new commands from being executed by the SDRAM, regardless of whether the CLK signal is enabled. The SDRAM is effectively deselected. Operations already in progress are not affected.

NO Operation (NOP)

The NO OPERATION (NOP) command is used to instruct the selected SDRAM to perform a NOP (RAS#, CAS#, and WE# are HIGH, CS# is LOW). This prevents unwanted commands from being registered during idle or wait states. Operations already in progress are not affected.

LOAD mode register

The mode register is loaded via inputs A0–A11. Refer to “Mode Register Definition” on page 13. The LOAD MODE REGISTER and LOAD EXTENDED MODE REGISTER commands can only be issued when all banks are idle, and a subsequent executable command cannot be issued until ^tMRD is met.

ACTIVE

The ACTIVE command is used to open (or activate) a row in a particular bank for a subsequent access. The value on the BA0, BA1 inputs selects the bank, and the address provided on inputs A0–A11 selects the row. This row remains active (or open) for accesses until a PRECHARGE command is issued to that bank. A PRECHARGE command must be issued before opening a different row in the same bank.

READ

The READ command is used to initiate a burst read access to an active row. The value on the BA0, BA1 inputs selects the bank, and the address provided on inputs A0–A8 (x16) or A0–A7 (x32) selects the starting column location. The value on input A10 determines whether or not auto precharge is used. If auto precharge is selected, the row being accessed will be precharged at the end of the read burst; if auto precharge is not selected, the row will remain open for subsequent accesses. Read data appears on the DQs subject to the logic level on the DQM inputs two clocks earlier. If a given DQM signal was registered HIGH, the corresponding DQs will be High-Z two clocks later; if the DQM signal was registered LOW, the DQs will provide valid data.

WRITE

The WRITE command is used to initiate a burst write access to an active row. The value on the BA0, BA1 inputs selects the bank, and the address provided on inputs A0–A8 (x16) or A0–A7 (x32) selects the starting column location. The value on input A10 determines whether or not auto precharge is used. If auto precharge is selected, the row being accessed will be precharged at the end of the write burst; if auto precharge is not selected, the row will remain open for subsequent accesses. Input data appearing on the DQs is written to the memory array subject to the DQM input logic level appearing coincident with the data. If a given DQM signal is registered LOW, the corresponding data will be written to memory; if the DQM signal is registered HIGH, the corresponding data inputs will be ignored, and a write will not be executed to that byte/column location.

PRECHARGE

The PRECHARGE command is used to deactivate the open row in a particular bank or the open row in all banks. The bank(s) will be available for a subsequent row access a specified time (^tRP) after the PRECHARGE command is issued. Input A10 determines whether one or all banks are to be precharged, and in the case where only one bank is to be precharged, inputs BA0, BA1 select the bank. Otherwise BA0, BA1 are treated as “Don’t Care.” Once a bank has been precharged, it is in the idle state and must be activated prior to any READ or WRITE commands being issued to that bank.

Auto Precharge

Auto precharge is a feature which performs the same individual-bank precharge function described above, without requiring an explicit command. This is accomplished by using A10 to enable auto precharge in conjunction with a specific READ or WRITE command. A precharge of the bank/row that is addressed with the READ or WRITE command is automatically performed upon completion of the READ or WRITE burst, except in the full-page burst mode, where auto precharge does not apply. Auto precharge is non-persistent in that it is either enabled or disabled for each individual Read or Write command.

Auto precharge ensures that the precharge is initiated at the earliest valid stage within a burst. The user must not issue another command to the same bank until the precharge time (^tRP) is completed. This is determined as if an explicit PRECHARGE command was issued at the earliest possible time, as described for each burst type in the Operation section of this data sheet.

BURST TERMINATE

The BURST TERMINATE command is used to truncate either fixed-length or full-page bursts. The most recently registered READ or WRITE command prior to the BURST TERMINATE command will be truncated, as shown in the Operation section of this data sheet.

AUTO REFRESH

AUTO REFRESH is used during normal operation of the SDRAM and is analogous to CAS#-BEFORE-RAS# (CBR) refresh in conventional DRAMs. This command is nonpersistent, so it must be issued each time a refresh is required. All active banks must be PRECHARGED prior to issuing an AUTO REFRESH command. The AUTO REFRESH command should not be issued until the minimum t_{RP} has been met after the PRECHARGE command as shown in the operation section.

The addressing is generated by the internal refresh controller. This makes the address bits “Don’t Care” during an AUTO REFRESH command. The 128Mb SDRAM requires 4,096 AUTO REFRESH cycles every 64ms (t_{REF}), regardless of width option. Providing a distributed AUTO REFRESH command every 15.625 μ s will meet the refresh requirement and ensure that each row is refreshed. Alternatively, 4,096 AUTO REFRESH commands can be issued in a burst at the minimum cycle rate (t_{RFC}), once every 64ms.

SELF REFRESH

The SELF REFRESH command can be used to retain data in the SDRAM, even if the rest of the system is powered down. When in the self refresh mode, the SDRAM retains data without external clocking. The SELF REFRESH command is initiated like an AUTO REFRESH command except CKE is disabled (LOW). Once the SELF REFRESH command is registered, all the inputs to the SDRAM become “Don’t Care” with the exception of CKE, which must remain LOW.

Once self refresh mode is engaged, the SDRAM provides its own internal clocking, causing it to perform its own auto refresh cycles. The SDRAM must remain in self refresh mode for a minimum period equal to t_{RAS} and may remain in self refresh mode for an indefinite period beyond that.

The procedure for exiting self refresh requires a sequence of commands. First, CLK must be stable (stable clock is defined as a signal cycling within timing constraints specified for the clock pin) prior to CKE going back HIGH. Once CKE is HIGH, the SDRAM must have NOP commands issued (a minimum of two clocks, regardless of clock frequency) for t_{XSR} because time is required for the completion of any internal refresh in progress.

Upon exiting the self refresh mode, AUTO REFRESH commands must be issued every 15.625 μ s or less as both SELF REFRESH and AUTO REFRESH utilize the row refresh counter.

Operation

BANK/ROW ACTIVATION

Before any READ or WRITE commands can be issued to a bank within the SDRAM, a row in that bank must be “opened.” This is accomplished via the ACTIVE command, which selects both the bank and the row to be activated (see Figure 10).

After opening a row (issuing an ACTIVE command), a READ or WRITE command may be issued to that row, subject to the t_{RCD} specification. $t_{RCD}(\text{MIN})$ should be divided by the clock period and rounded up to the next whole number to determine the earliest clock edge after the ACTIVE command on which a READ or WRITE command can be entered. For example, a t_{RCD} specification of 20ns with a 125 MHz clock (8ns period) results in 2.5 clocks, rounded to 3. This is reflected in Figure 11, which covers any case where $2 < t_{RCD}(\text{MIN})/t_{CK} \leq 3$. (The same procedure is used to convert other specification limits from time units to clock cycles.)

A subsequent ACTIVE command to a different row in the same bank can only be issued after the previous active row has been “closed” (precharged). The minimum time interval between successive ACTIVE commands to the same bank is defined by t_{RC} .

A subsequent ACTIVE command to another bank can be issued while the first bank is being accessed, which results in a reduction of total row-access over-

head. The minimum time interval between successive ACTIVE commands to different banks is defined by t_{RRD} .

Figure 10: Activating a Specific Row in a Specific Bank

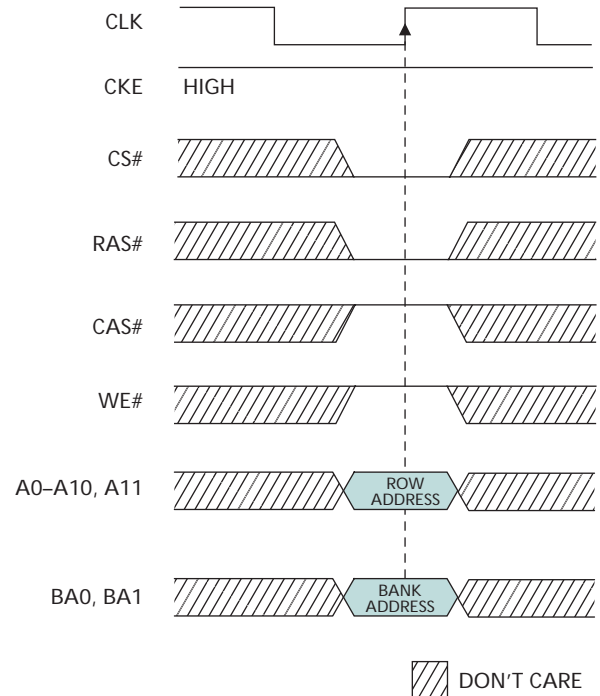
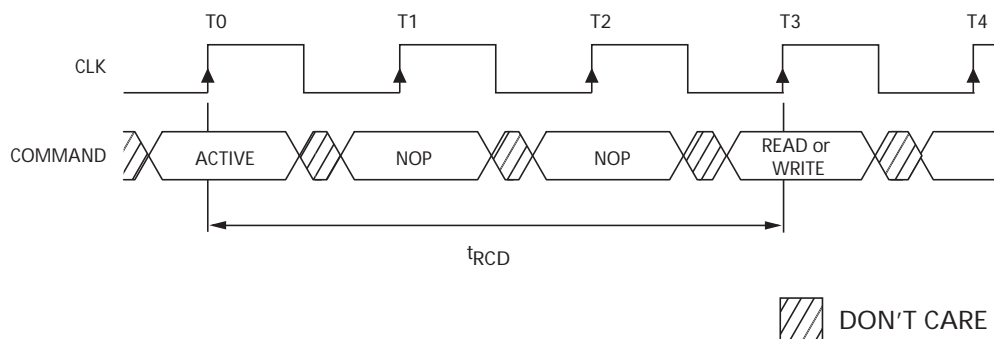


Figure 11: Example: Meeting $t_{RCD}(\text{MIN})$ When $2 < t_{RCD}(\text{MIN})/t_{CK} \leq 3$



READs

READ bursts are initiated with a READ command, as shown in Figure 12.

The starting column and bank addresses are provided with the READ command, and auto precharge is either enabled or disabled for that burst access. If auto precharge is enabled, the row being accessed is precharged at the completion of the burst. For the READ commands used in the following illustrations, auto precharge is disabled.

During READ bursts, the valid data-out element from the starting column address will be available following the CAS latency after the READ command. Each subsequent data-out element will be valid by the next positive clock edge. Figure 13 shows general timing for each possible CAS latency setting.

Upon completion of a burst, assuming no other commands have been initiated, the DQs will go High-Z. A full-page burst will continue until terminated. (At the end of the page, it will wrap to column 0 and continue.)

Data from any READ burst may be truncated with a subsequent READ command, and data from a fixed-length READ burst may be immediately followed by data from a READ command. In either case, a continuous flow of data can be maintained. The first data element from the new burst follows either the last element of a completed burst or the last desired data element of a longer burst that is being truncated. The new READ command should be issued x cycles before the clock edge at which the last desired data element is valid, where x equals the CAS latency minus one.

Figure 12: READ Command

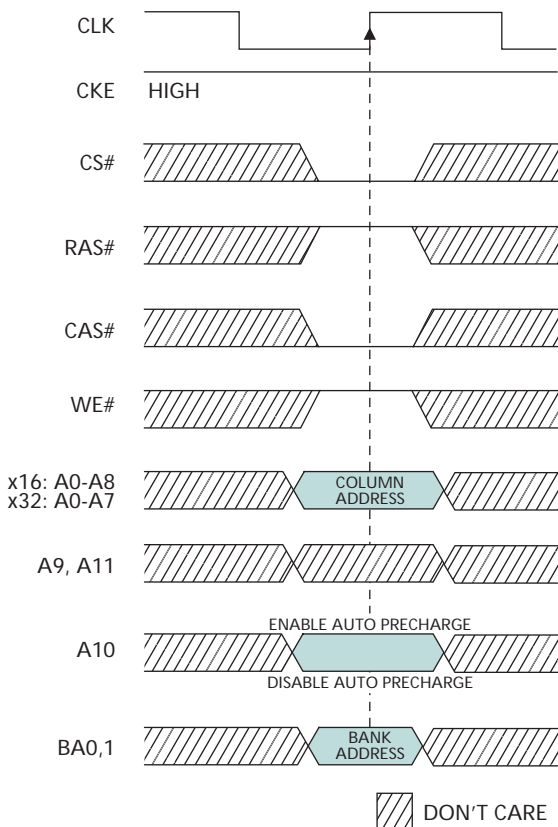
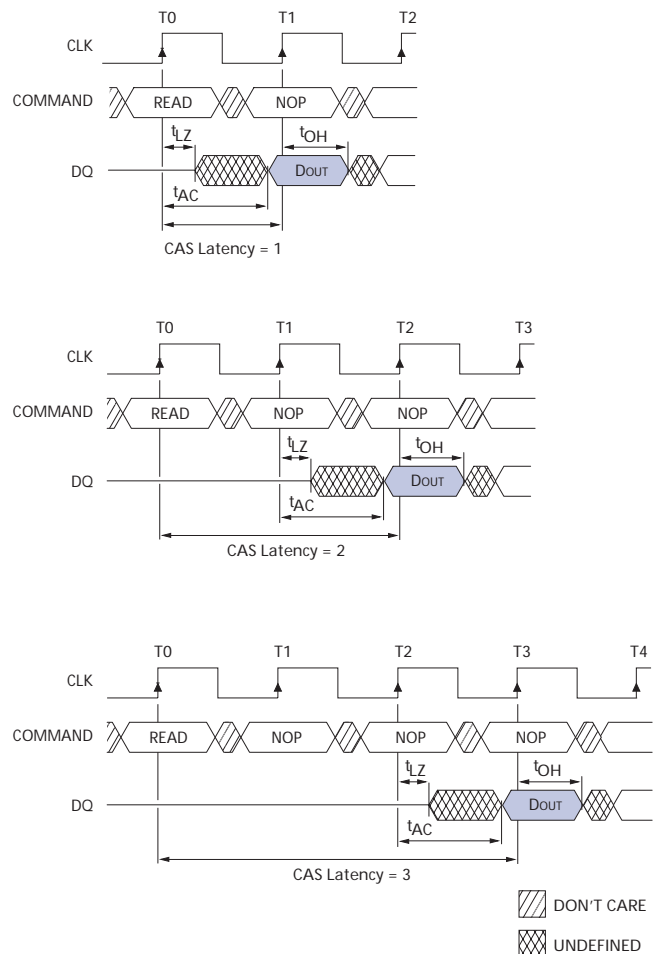


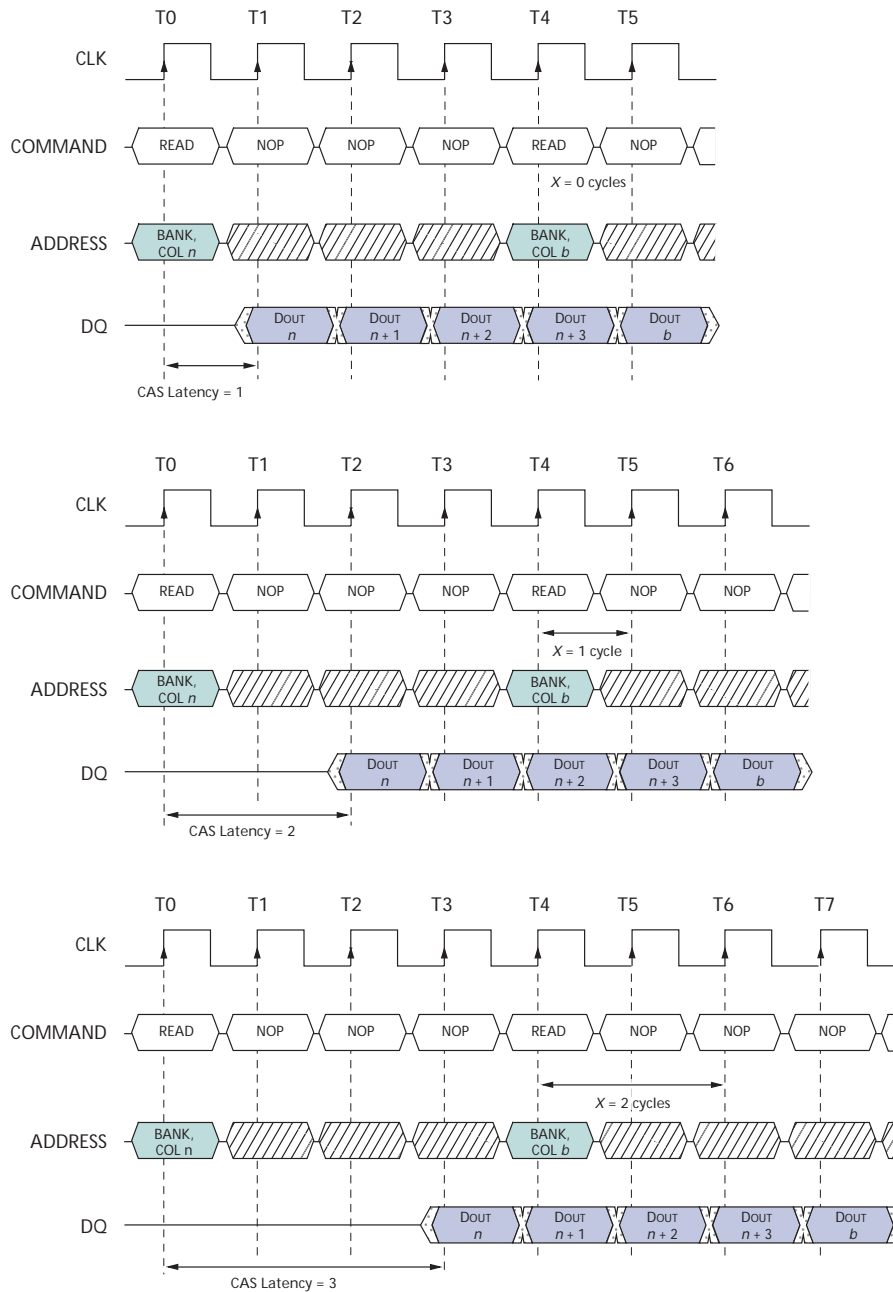
Figure 13: CAS Latency



This is shown in Figure 14 for CAS latencies of two and three; data element $n + 3$ is either the last of a burst of four or the last desired of a longer burst. The 128Mb SDRAM uses a pipelined architecture and therefore does not require the $2n$ rule associated with a prefetch

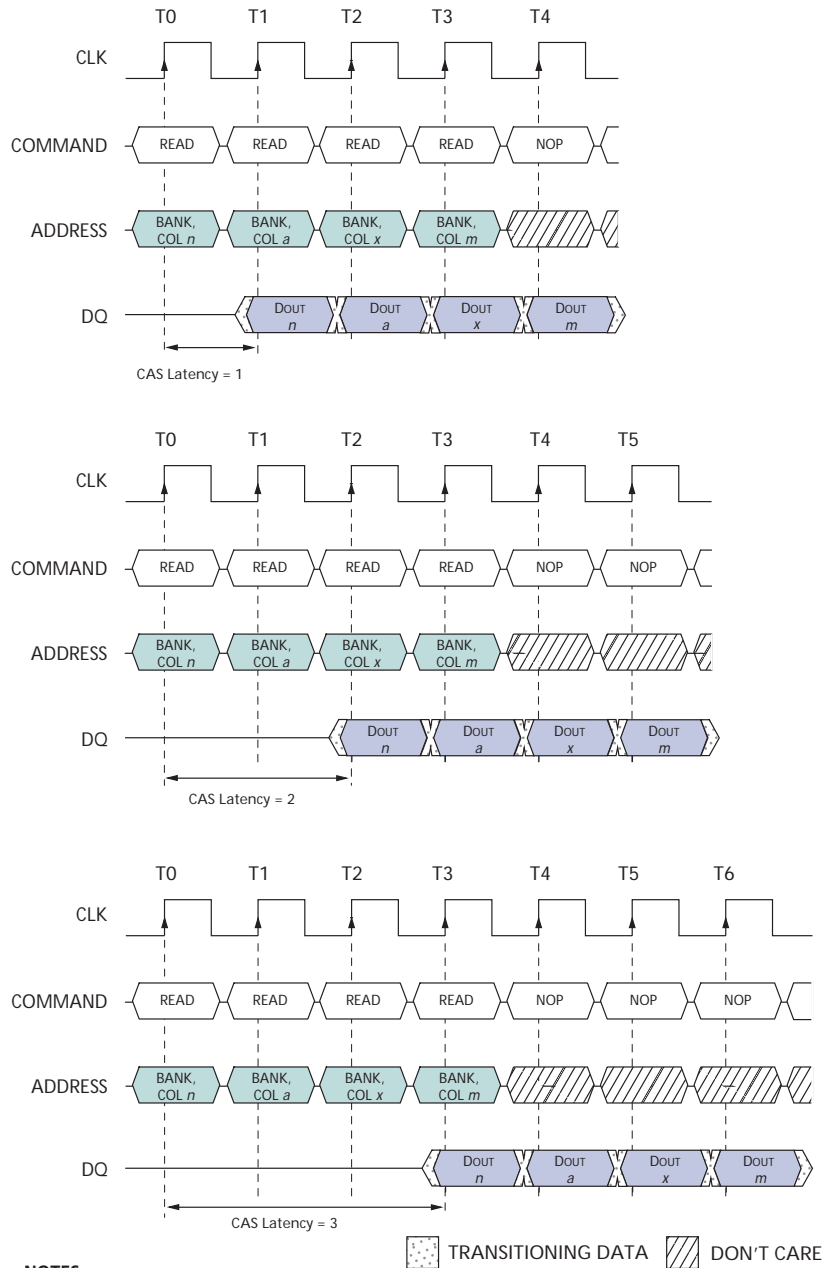
architecture. A READ command can be initiated on any clock cycle following a previous READ command. Full-speed random read accesses can be performed to the same bank, as shown in Figure 15, or each subsequent READ may be performed to a different bank.

Figure 14: Consecutive READ Bursts

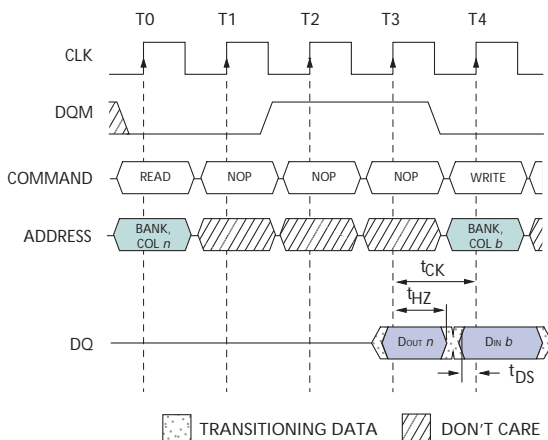


NOTE: Each READ command may be to either bank. DQM is LOW. Shown with BL=4.

TRANSITIONING DATA DON'T CARE

Figure 15: Random READ Accesses


Data from any READ burst may be truncated with a subsequent WRITE command, and data from a fixed-length READ burst may be immediately followed by data from a WRITE command (subject to bus turn-around limitations). The WRITE burst may be initiated on the clock edge immediately following the last (or last desired) data element from the READ burst, provided that I/O contention can be avoided. In a given system design, there may be a possibility that the device driving the input data will go Low-Z before the SDRAM DQs go High-Z. In this case, at least a single-cycle delay should occur between the last read data and the WRITE command.

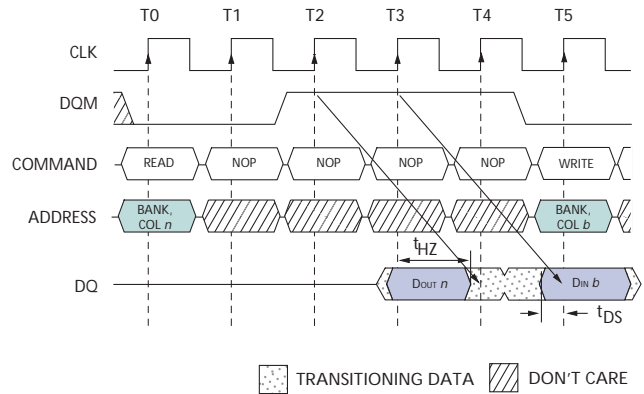
Figure 16: READ to WRITE


- NOTES:
- 1) A CAS latency of three is used for illustration.
 - 2) The READ command may be to any bank, and the WRITE command may be to any bank.
 - 3) If a burst of one is used, then DQM is not required.

The DQM input is used to avoid I/O contention, as shown in Figure 16 and Figure 17. The DQM signal must be asserted (HIGH) at least two clocks prior to the WRITE command (DQM latency is two clocks for output buffers) to suppress data-out from the READ. Once the WRITE command is registered, the DQs will go High-Z (or remain High-Z), regardless of the state of the DQM signal, provided the DQM was active on the clock just prior to the WRITE command that truncated the READ command. If not, the second WRITE will be an invalid WRITE. For example, if DQM was LOW during T4 in Figure 17, then the WRITES at T5 and T7 would be valid, while the WRITE at T6 would be invalid.

The DQM signal must be de-asserted prior to the WRITE command (DQM latency is zero clocks for input buffers) to ensure that the written data is not

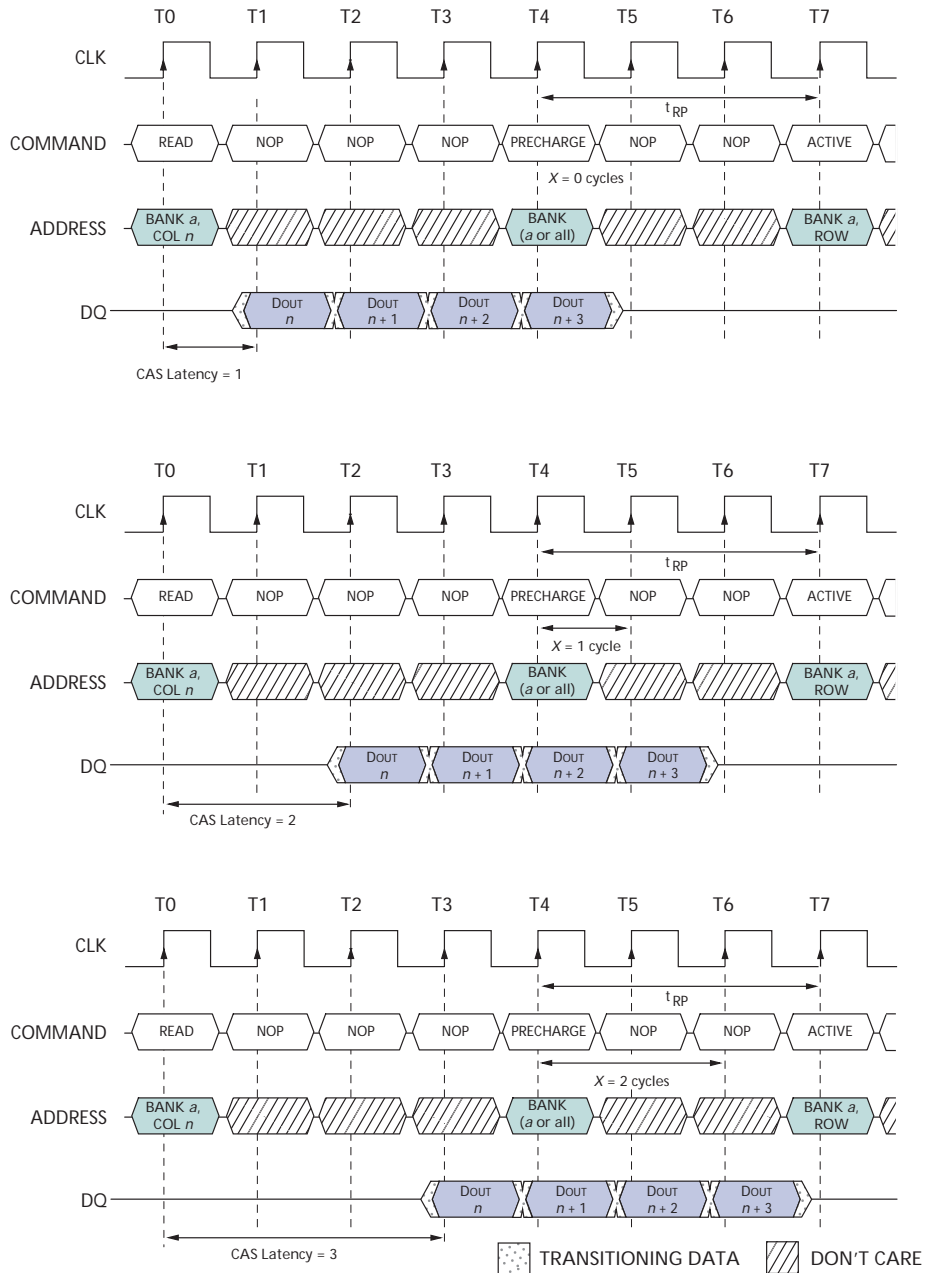
masked. Figure 16 shows the case where the clock frequency allows for bus contention to be avoided without adding a NOP cycle, and Figure 17 shows the case where the additional NOP is needed.

Figure 17: READ to WRITE with Extra Clock Cycle


- NOTE: A CAS latency of three is used for illustration. The READ command may be to any bank, and the WRITE command may be to any bank.

A fixed-length READ burst may be followed by, or truncated with, a PRECHARGE command to the same bank (provided that auto precharge was not activated), and a full-page burst may be truncated with a PRECHARGE command to the same bank. The PRECHARGE command should be issued x cycles before the clock edge at which the last desired data element is valid, where x equals the CAS latency minus one. This is shown in Figure 18 for each possible CAS latency; data element $n + 3$ is either the last of a burst of four or the last desired of a longer burst. Following the PRECHARGE command, a subsequent command to the same bank cannot be issued until t_{RP} is met. Note that part of the row precharge time is hidden during the access of the last data element(s).

In the case of a fixed-length burst being executed to completion, a PRECHARGE command issued at the optimum time (as described above) provides the same operation that would result from the same fixed-length burst with auto precharge. The disadvantage of the PRECHARGE command is that it requires that the command and address buses be available at the appropriate time to issue the command; the advantage of the PRECHARGE command is that it can be used to truncate fixed-length or full-page bursts.

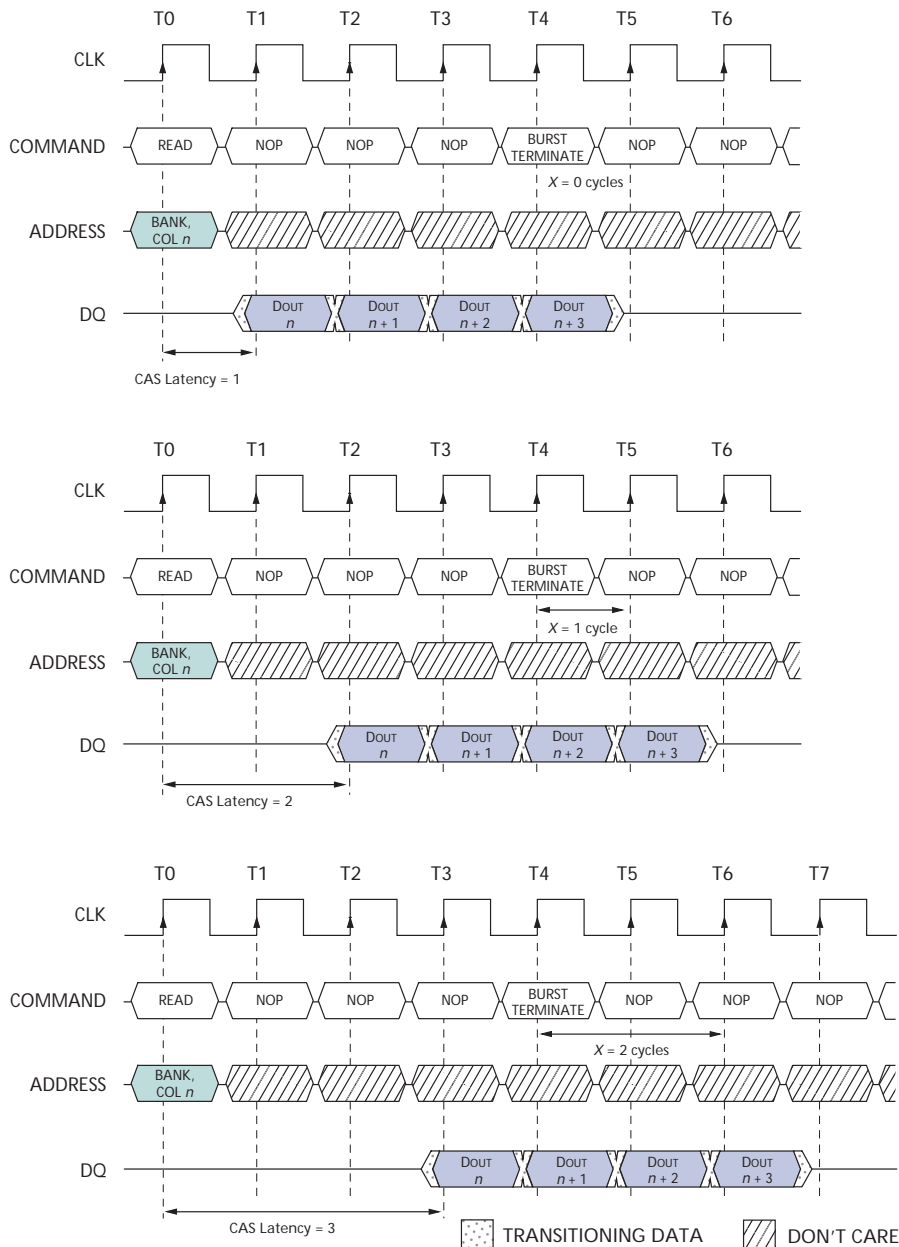
Figure 18: READ to PRECHARGE


- NOTES:**
- 1) Assumes $t_{RAS}(\min)$ has been satisfied prior to the precharge command
 - 2) N+3 is either the last data element of a BL=4, or the last desired data element of a longer burst
 - 3) DQM is LOW.

Full-page READ bursts can be truncated with the BURST TERMINATE command, and fixed-length READ bursts may be truncated with a BURST TERMINATE command, provided that auto precharge was not activated. The BURST TERMINATE command

should be issued x cycles before the clock edge at which the last desired data element is valid, where x equals the CAS latency minus one. This is shown in Figure 19 for each possible CAS latency; data element $n + 3$ is the last desired data element of a longer burst.

Figure 19: Terminating a READ Burst



- NOTES:**
- 1) Page remains open after a Burst Terminate command
 - 2) N+3 is either the last data element of a burst of four, or the last desired data element of a longer burst.
 - 3) DQM is LOW.

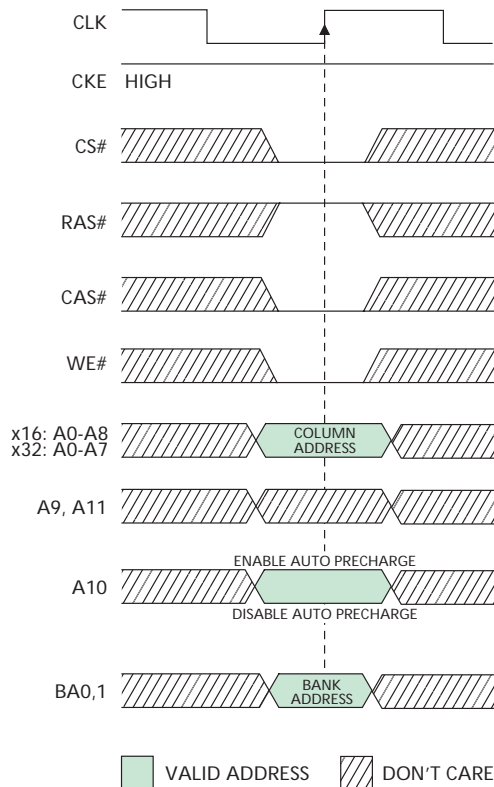
WRITES

WRITE bursts are initiated with a WRITE command, as shown in Figure 20.

The starting column and bank addresses are provided with the WRITE command, and auto precharge is either enabled or disabled for that access. If auto precharge is enabled, the row being accessed is precharged at the completion of the burst. For the WRITE commands used in the following illustrations, auto precharge is disabled.

During WRITE bursts, the first valid data-in element will be registered coincident with the WRITE command. Subsequent data elements will be registered on each successive positive clock edge. Upon completion of a fixed-length burst, assuming no other commands have been initiated, the DQs will remain High-Z and any additional input data will be ignored (see Figure 21). A full-page burst will continue until terminated. (At the end of the page, it will wrap to column 0 and continue.)

Figure 20: WRITE Command



Data for any WRITE burst may be truncated with a subsequent WRITE command, and data for a fixed-length WRITE burst may be immediately followed by data for a WRITE command. The new WRITE com-

mand can be issued on any clock following the previous WRITE command, and the data provided coincident with the new command applies to the new command. An example is shown in Figure 21. Data $n + 1$ is either the last of a burst of two or the last desired of a longer burst. The 128Mb SDRAM uses a pipelined architecture and therefore does not require the $2n$ rule associated with a prefetch architecture. A WRITE command can be initiated on any clock cycle following a previous WRITE command. Full-speed random write accesses within a page can be performed to the same bank, as shown in Figure 22, or each subsequent WRITE may be performed to a different bank.

Figure 21: WRITE Burst

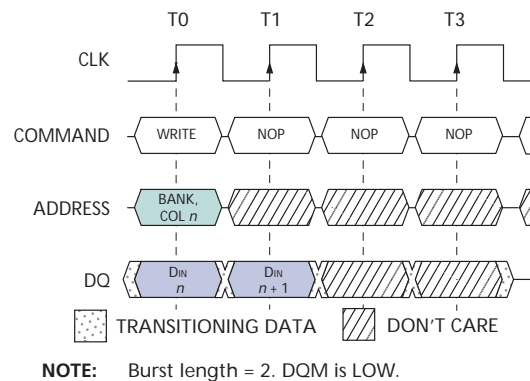
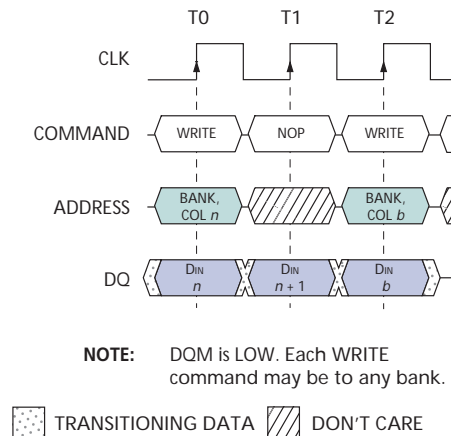


Figure 22: WRITE to WRITE



Data for any WRITE burst may be truncated with a subsequent READ command, and data for a fixed-length WRITE burst may be immediately followed by a READ command. Once the READ command is registered, the data inputs will be ignored, and writes will

not be executed. An example is shown in Figure 24. Data $n + 1$ is either the last of a burst of two or the last desired of a longer burst.

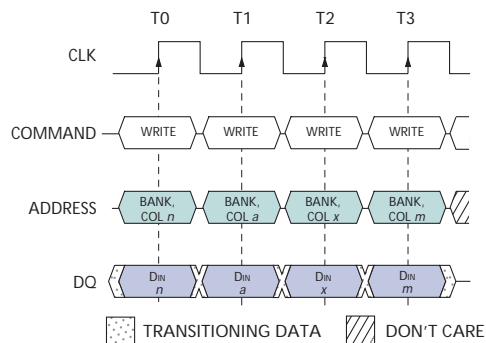
Data for a fixed-length WRITE burst may be followed by, or truncated with, a PRECHARGE command to the same bank (provided that auto precharge was not activated), and a full-page WRITE burst may be truncated with a PRECHARGE command to the same bank. The PRECHARGE command should be issued t_{WR} after the clock edge at which the last desired input data element is registered. The auto precharge mode requires a t_{WR} of at least one clock plus time, regardless of frequency.

In addition, when truncating a WRITE burst, the DQM signal must be used to mask input data for the clock edge prior to, and the clock edge coincident with,

the PRECHARGE command. An example is shown in Figure 25. Data $n + 1$ is either the last of a burst of two or the last desired of a longer burst. Following the PRECHARGE command, a subsequent command to the same bank cannot be issued until t_{RP} is met.

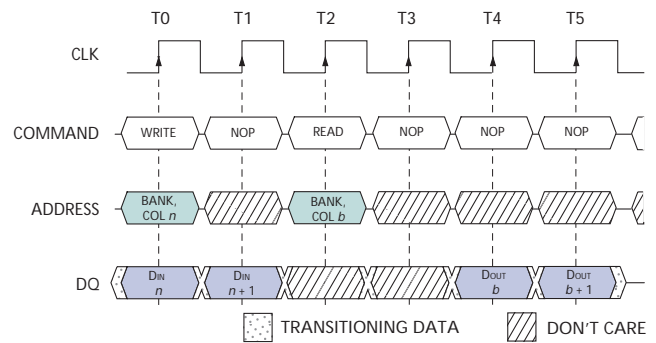
In the case of a fixed-length burst being executed to completion, a PRECHARGE command issued at the optimum time (as described above) provides the same operation that would result from the same fixed-length burst with auto precharge. The disadvantage of the PRECHARGE command is that it requires that the command and address buses be available at the appropriate time to issue the command; the advantage of the PRECHARGE command is that it can be used to truncate fixed-length or full-page bursts.

Figure 23: Random WRITE Cycles



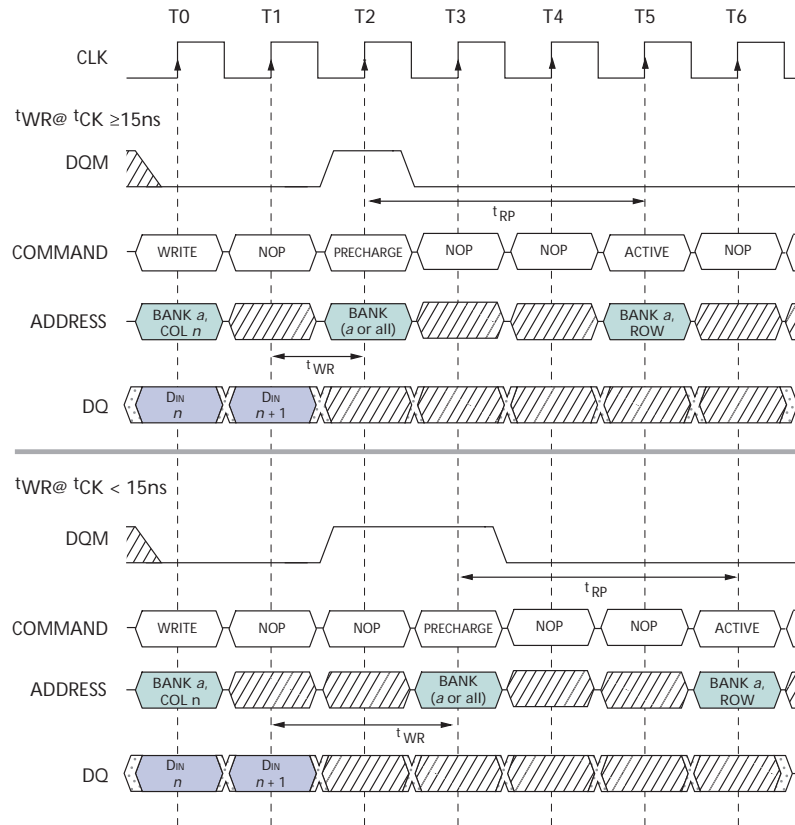
- NOTES:**
- 1) Each WRITE command may be to any bank.
 - 2) DQM is LOW.
 - 3) Example shows a burst of one, or an interrupting BL > 1.

Figure 24: WRITE to READ



- NOTES:**
- 1) The WRITE command may be to any bank, and the READ command may be to any bank.
 - 2) DQM is LOW.
 - 3) CAS latency = 2 for illustration.
 - 4) Data $n+1$ is either the last data of a burst of two, or the last desired of a longer burst.

Figure 25: WRITE to PRECHARGE



NOTE: DQM could remain LOW in this example if the WRITE burst is a fixed length of two.

TRANSITIONING DATA DON'T CARE

Fixed-length or full-page WRITE bursts can be truncated with the BURST TERMINATE command. When truncating a WRITE burst, the input data applied coincident with the BURST TERMINATE command will be ignored. The last data written (provided that DQM is LOW at that time) will be the input data applied one clock previous to the BURST TERMINATE command. This is shown in Figure 26, where data n is the last desired data element of a longer burst.

Figure 26: Terminating a WRITE Burst

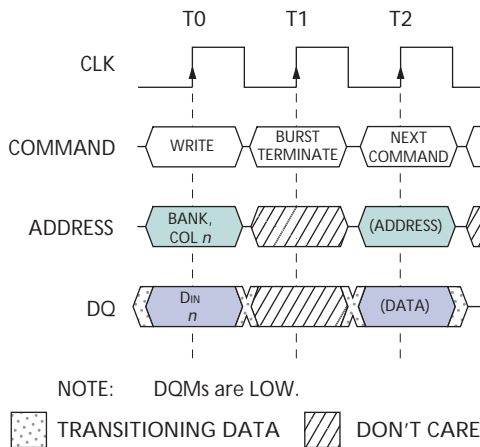
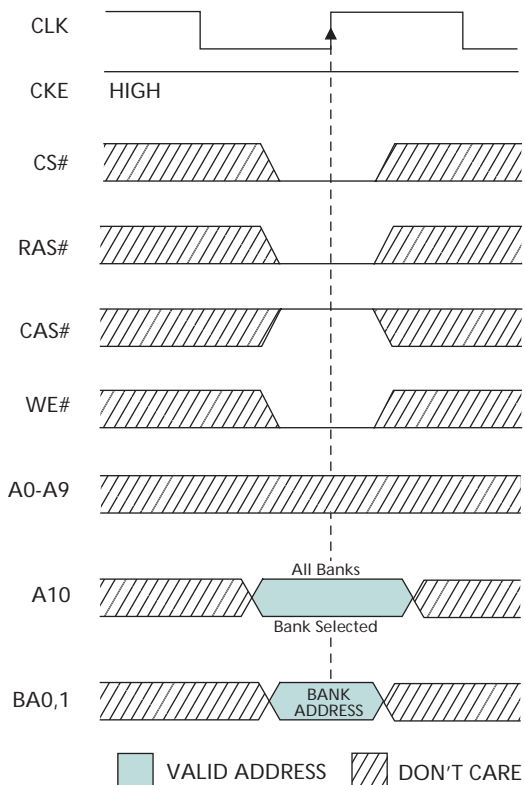


Figure 27: PRECHARGE Command



PRECHARGE

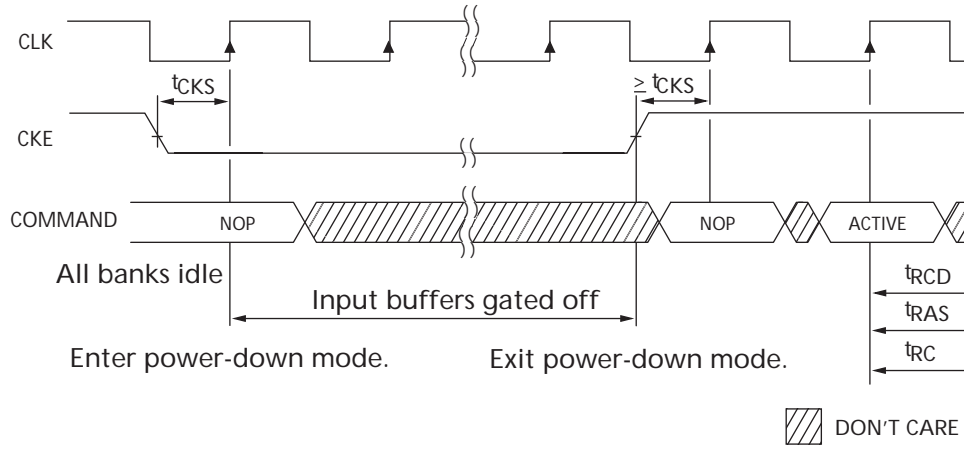
The PRECHARGE command (see Figure 27) is used to deactivate the open row in a particular bank or the open row in all banks. The bank(s) will be available for a subsequent row access some specified time (t_{RP}) after the precharge command is issued. Input A10 determines whether one or all banks are to be precharged, and in the case where only one bank is to be precharged, inputs BA0, BA1 select the bank. When all banks are to be precharged, inputs BA0, BA1 are treated as “Don’t Care.” Once a bank has been precharged, it is in the idle state and must be activated prior to any READ or WRITE commands being issued to that bank.

POWER-DOWN

Power-down occurs if CKE is registered low coincident with a NOP or COMMAND INHIBIT when no accesses are in progress. If power-down occurs when all banks are idle, this mode is referred to as precharge power-down; if power-down occurs when there is a row active in any bank, this mode is referred to as active power-down. Entering power-down deactivates the input and output buffers, excluding CKE, for maximum power savings while in standby. The device may not remain in the power-down state longer than the refresh period (64ms) since no refresh operations are performed in this mode.

The power-down state is exited by registering a NOP or COMMAND INHIBIT and CKE HIGH at the desired clock edge (meeting t_{CKS}). See Figure 28.

Figure 28: Power-Down

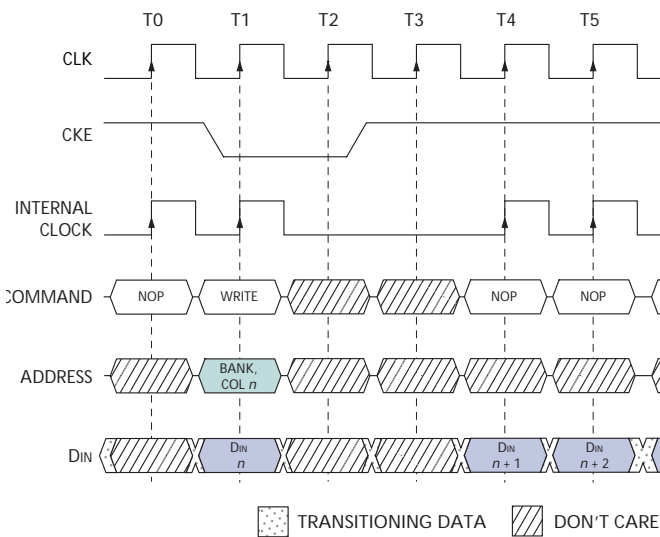


CLOCK SUSPEND

The clock suspend mode occurs when a column access/burst is in progress and CKE is registered low. In the clock suspend mode, the internal clock is deactivated, “freezing” the synchronous logic.

For each positive clock edge on which CKE is sampled LOW, the next internal positive clock edge is suspended. Any command or data present on the input pins at the time of a suspended internal clock edge is ignored; any data present on the DQ pins remains driven; and burst counters are not incremented, as long as the clock is suspended. (See examples in Figure 29 and Figure 30.)

Figure 29: Clock Suspend During WRITE Burst



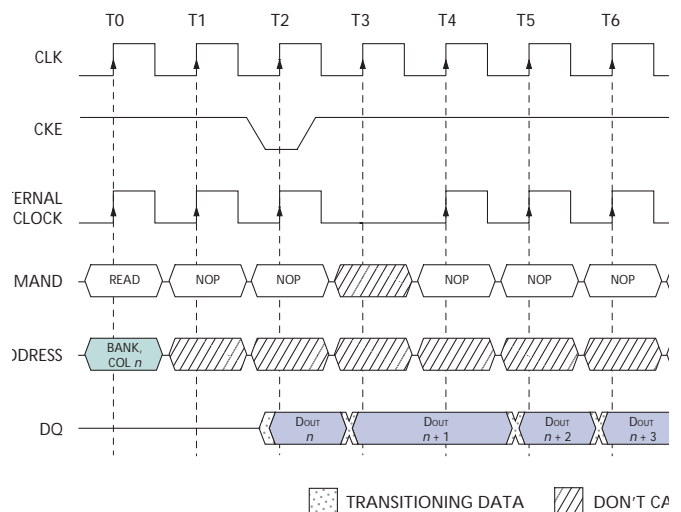
NOTE: For this example, burst length = 4 or greater, and DM is LOW.

Clock suspend mode is exited by registering CKE HIGH; the internal clock and related operation will resume on the subsequent positive clock edge.

BURST READ/SINGLE WRITE

The burst read/single write mode is entered by programming the write burst mode bit (M9) in the mode register to a logic 1. In this mode, all WRITE commands result in the access of a single column location (burst of one), regardless of the programmed burst length. READ commands access columns according to the programmed burst length and sequence, just as in the normal mode of operation (M9 = 0).

Figure 30: Clock Suspend During READ Burst



NOTE: For this example, CAS latency = 2, burst length = 4 or greater, and DQM is LOW.

CONCURRENT Auto Precharge

An access command (READ or WRITE) to another bank while an access command with auto precharge enabled is executing is not allowed by SDRAMs, unless the SDRAM supports Concurrent Auto precharge. Micron SDRAMs support Concurrent Auto precharge. Four cases where Concurrent Auto precharge occurs are defined below.

READ with Auto Precharge

1. Interrupted by a READ (with or without auto precharge): A READ to bank *m* will interrupt a READ on bank *n*, CAS latency later. The precharge to bank *n* will begin when the READ to bank *m* is registered (Figure 31).

2. Interrupted by a WRITE (with or without auto precharge): A WRITE to bank *m* will interrupt a READ on bank *n* when registered. DQM should be used two clocks prior to the WRITE command to prevent bus contention. The precharge to bank *n* will begin when the WRITE to bank *m* is registered (Figure 32).

Figure 31: READ With Auto Precharge Interrupted by a READ

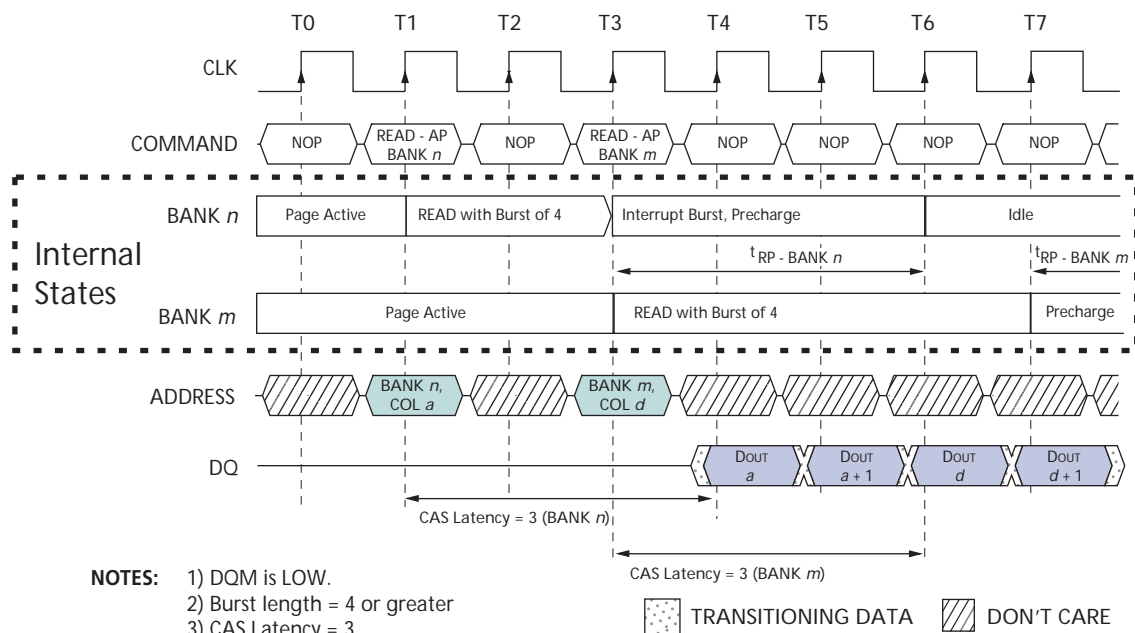
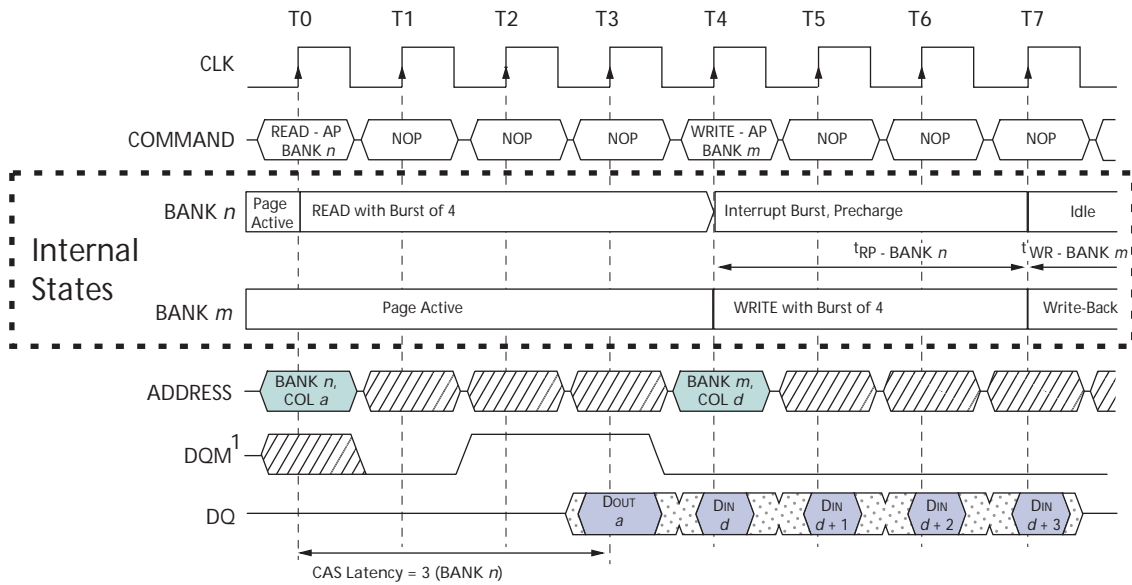


Figure 32: READ With Auto Precharge Interrupted by a WRITE

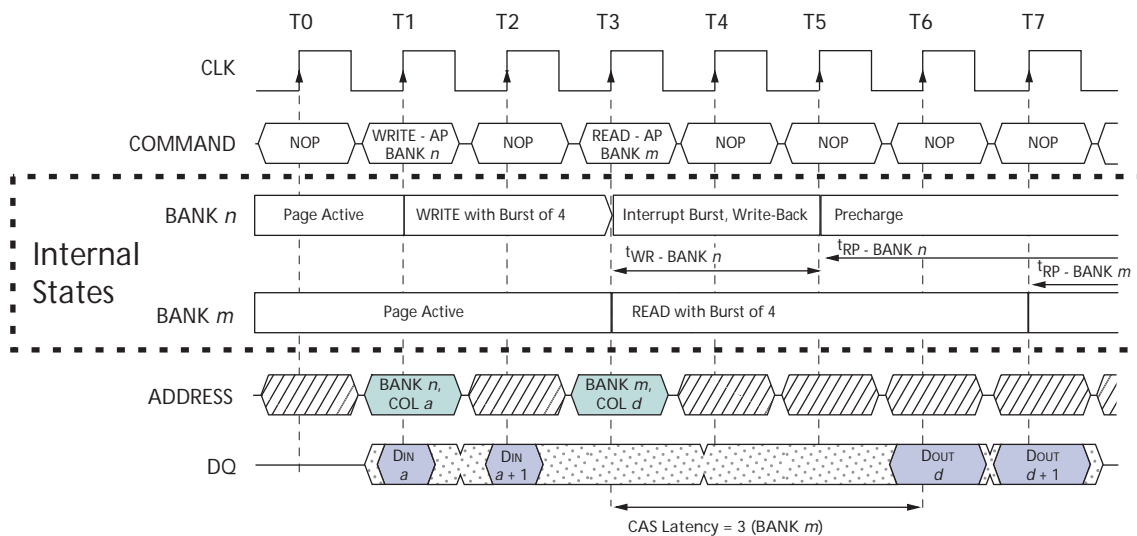


NOTE: 1. DQM is HIGH at T2 to prevent DOUT-a+1 from contending with DIN-d at T4.

TRANSITIONING DATA DON'T CARE

WRITE with Auto Precharge

3. Interrupted by a READ (with or without auto pre-charge): A READ to bank *m* will interrupt a WRITE on bank *n* when registered, with the data-out appearing CAS latency later. The precharge to bank *n* will begin after t_{WR} is met, where t_{WR} begins when the READ to bank *m* is registered. The last valid WRITE to bank *n* will be data-in registered one clock prior to the READ to bank *m* (Figure 33).
4. Interrupted by a WRITE (with or without auto pre-charge): A WRITE to bank *m* will interrupt a WRITE on bank *n* when registered. The precharge to bank *n* will begin after t_{WR} is met, where t_{WR} begins when the WRITE to bank *m* is registered. The last valid data WRITE to bank *n* will be data registered one clock prior to a WRITE to bank *m* (Figure 34).

Figure 33: WRITE With Auto Precharge Interrupted by a READ


NOTE: 1. DQM is LOW.

TRANSITIONING DATA DON'T CARE

Figure 34: WRITE With Auto Precharge Interrupted by a WRITE

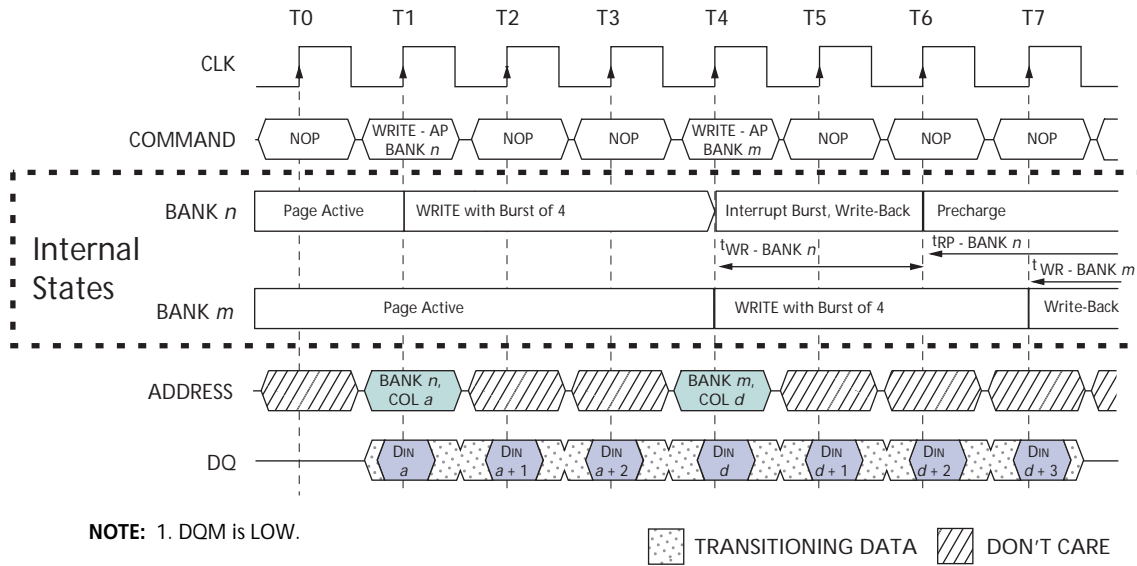


Table 9: Truth Table – CKE

(Notes: 1-4)

CKE _{n-1}	CKE _n	CURRENT STATE	COMMAND _n	ACTION _n	NOTES
L	L	Power-Down	X	Maintain Power-Down	
		Self Refresh	X	Maintain Self Refresh	
		Clock Suspend	X	Maintain Clock Suspend	
L	H	Power-Down	COMMAND INHIBIT or NOP	Exit Power-Down	5
		Self Refresh	COMMAND INHIBIT or NOP	Exit Self Refresh	6
		Clock Suspend	X	Exit Clock Suspend	7
H	L	All Banks Idle	COMMAND INHIBIT or NOP	Power-Down Entry	
		All Banks Idle	AUTO REFRESH	Self Refresh Entry	
		Reading or Writing	VALID	Clock Suspend Entry	
H	H		See Table 10 on page 38		

NOTE:

1. CKE_n is the logic state of CKE at clock edge *n*; CKE_{n-1} was the state of CKE at the previous clock edge.
2. Current state is the state of the SDRAM immediately prior to clock edge *n*.
3. COMMAND_n is the command registered at clock edge *n*, and ACTION_n is a result of COMMAND_n.
4. All states and sequences not shown are illegal or reserved.
5. Exiting power-down at clock edge *n* will put the device in the all banks idle state in time for clock edge *n* + 1 (provided that ^tCKS is met).
6. Exiting self refresh at clock edge *n* will put the device in the all banks idle state once ^tXSR is met. COMMAND INHIBIT or NOP commands should be issued on any clock edges occurring during the ^tXSR period. A minimum of two NOP commands must be provided during ^tXSR period.
7. After exiting clock suspend at clock edge *n*, the device will resume operation and recognize the next command at clock edge *n* + 1.

Table 10: Truth Table – Current State Bank *n*, Command To Bank *n*

Notes: 1-6; notes appear below table

CURRENT STATE	CS#	RAS#	CAS#	WE#	COMMAND (ACTION)	NOTES
Any	H	X	X	X	COMMAND INHIBIT (NOP/Continue previous operation)	
	L	H	H	H	NO OPERATION (NOP/Continue previous operation)	
Idle	L	L	H	H	ACTIVE (Select and activate row)	
	L	L	L	H	AUTO REFRESH	7
	L	L	L	L	LOAD MODE REGISTER	7
	L	L	H	L	PRECHARGE	11
Row Active	L	H	L	H	READ (Select column and start READ burst)	10
	L	H	L	L	WRITE (Select column and start WRITE burst)	10
	L	L	H	L	PRECHARGE (Deactivate row in bank or banks)	8
Read (Auto Precharge Disabled)	L	H	L	H	READ (Select column and start new READ burst)	10
	L	H	L	L	WRITE (Select column and start WRITE burst)	10
	L	L	H	L	PRECHARGE (Truncate READ burst, start PRECHARGE)	8
	L	H	H	L	BURST TERMINATE	9
Write (Auto Precharge Disabled)	L	H	L	H	READ (Select column and start READ burst)	10
	L	H	L	L	WRITE (Select column and start new WRITE burst)	10
	L	L	H	L	PRECHARGE (Truncate WRITE burst, start PRECHARGE)	8
	L	H	H	L	BURST TERMINATE	9

NOTE:

- This table applies when CKE_{n-1} was HIGH and CKE_n is HIGH (see Table 9 on page 37) and after t_{XSR} has been met (if the previous state was self refresh).
- This table is bank-specific, except where noted; i.e., the current state is for a specific bank and the commands shown are those allowed to be issued to that bank when in that state. Exceptions are covered in the notes below.
- Current state definitions:
 - Idle: The bank has been precharged, and t_{RP} has been met.
 - Row Active: A row in the bank has been activated, and t_{RCD} has been met. No data bursts/accesses and no register accesses are in progress.
 - Read: A READ burst has been initiated, with auto precharge disabled, and has not yet terminated or been terminated.
 - Write: A WRITE burst has been initiated, with auto precharge disabled, and has not yet terminated or been terminated.
- The following states must not be interrupted by a command issued to the same bank. COMMAND INHIBIT or NOP commands, or allowable commands to the other bank should be issued on any clock edge occurring during these states. Allowable commands to the other bank are determined by its current state and Table 10 on page 38, and according to Table 11 on page 40.
 - Precharging: Starts with registration of a PRECHARGE command and ends when t_{RP} is met. Once t_{RP} is met, the bank will be in the idle state.
 - Row Activating: Starts with registration of an ACTIVE command and ends when t_{RCD} is met. Once t_{RCD} is met, the bank will be in the row active state.
 - Read w/Auto Precharge Enabled: Starts with registration of a READ command with auto precharge enabled and ends when t_{RP} has been met. Once t_{RP} is met, the bank will be in the idle state.
 - Write w/Auto Precharge Enabled: Starts with registration of a WRITE command with auto precharge enabled and ends when t_{RP} has been met. Once t_{RP} is met, the bank will be in the idle state.
- The following states must not be interrupted by any executable command; COMMAND INHIBIT or NOP commands must be applied on each positive clock edge during these states. Refreshing: Starts with registration of an AUTO REFRESH command and ends when t_{RFC} is met. Once t_{RFC} is met, the SDRAM will be in the all banks idle state.
 - Accessing Mode Register: Starts with registration of a LOAD MODE REGISTER command and ends when t_{MRD} has been met. Once t_{MRD} is met, the SDRAM will be in the all banks idle state.
 - Precharging All: Starts with registration of a PRECHARGE ALL command and ends when t_{RP} is met. Once t_{RP} is met, all banks will be in the idle state.
- All states and sequences not shown are illegal or reserved.

7. Not bank-specific; requires that all banks are idle.
8. May or may not be bank-specific; if all banks are to be precharged, all must be in a valid state for precharging.
9. Not bank-specific; BURST TERMINATE affects the most recent READ or WRITE burst, regardless of bank.
10. READs or WRITEs listed in the Command (Action) column include READs or WRITEs with auto precharge enabled and READs or WRITEs with auto precharge disabled.
11. Does not affect the state of the bank and acts as a NOP to that bank.

Table 11: Truth Table – CURRENT STATE BANK n, COMMAND TO BANK m

Notes: 1-6; notes appear below and on next page

CURRENT STATE	CS#	RAS#	CAS#	WE#	COMMAND (ACTION)	NOTES
Any	H	X	X	X	COMMAND INHIBIT (NOP/Continue previous operation)	
	L	H	H	H	NO OPERATION (NOP/Continue previous operation)	
Idle	X	X	X	X	Any Command Otherwise Allowed to Bank m	
Row Activating, Active, or Precharging	L	L	H	H	ACTIVE (Select and activate row)	
	L	H	L	H	READ (Select column and start READ burst)	7
	L	H	L	L	WRITE (Select column and start WRITE burst)	7
	L	L	H	L	PRECHARGE	
Read (Auto Precharge Disabled)	L	L	H	H	ACTIVE (Select and activate row)	
	L	H	L	H	READ (Select column and start new READ burst)	7, 10
	L	H	L	L	WRITE (Select column and start WRITE burst)	7, 11
	L	L	H	L	PRECHARGE	9
Write (Auto Precharge Disabled)	L	L	H	H	ACTIVE (Select and activate row)	
	L	H	L	H	READ (Select column and start READ burst)	7, 12
	L	H	L	L	WRITE (Select column and start new WRITE burst)	7, 13
	L	L	H	L	PRECHARGE	9
Read (With Auto Precharge)	L	L	H	H	ACTIVE (Select and activate row)	
	L	H	L	H	READ (Select column and start new READ burst)	7, 8, 14
	L	H	L	L	WRITE (Select column and start WRITE burst)	7, 8, 15
	L	L	H	L	PRECHARGE	9
Write (With Auto Precharge)	L	L	H	H	ACTIVE (Select and activate row)	
	L	H	L	H	READ (Select column and start READ burst)	7, 8, 16
	L	H	L	L	WRITE (Select column and start new WRITE burst)	7, 8, 17
	L	L	H	L	PRECHARGE	9

NOTE:

- This table applies when CKE_{n-1} was HIGH and CKE_n is HIGH (see Table 9 on page 37) and after t^1XSR has been met (if the previous state was self refresh).
- This table describes alternate bank operation, except where noted; i.e., the current state is for bank n and the commands shown are those allowed to be issued to bank m (assuming that bank m is in such a state that the given command is allowable). Exceptions are covered in the notes below.
- Current state definitions:
 - Idle: The bank has been precharged, and t^1RP has been met.
 - Row Active: A row in the bank has been activated, and t^1RCD has been met. No data bursts/accesses and no register accesses are in progress.
 - Read: A READ burst has been initiated, with auto precharge disabled, and has not yet terminated or been terminated.
 - Write: A WRITE burst has been initiated, with auto precharge disabled, and has not yet terminated or been terminated.
- Read w/Auto Precharge Enabled: Starts with registration of a READ command with auto precharge enabled, and ends when t^1RP has been met. Once t^1RP is met, the bank will be in the idle state.
- Write w/Auto Precharge Enabled: Starts with registration of a WRITE command with auto precharge enabled, and ends when t^1RP has been met. Once t^1RP is met, the bank will be in the idle state.
- AUTO REFRESH, SELF REFRESH and LOAD MODE REGISTER commands may only be issued when all banks are idle.
- A BURST TERMINATE command cannot be issued to another bank; it applies to the bank represented by the current state only.
- All states and sequences not shown are illegal or reserved.

7. READs or WRITEs to bank m listed in the Command (Action) column include READs or WRITEs with auto precharge enabled and READs or WRITEs with auto precharge disabled.
8. CONCURRENT AUTO PRECHARGE: Bank n will initiate the auto precharge command when its burst has been interrupted by bank m's burst.
9. Burst in bank n continues as initiated.
10. For a READ without auto precharge interrupted by a READ (with or without auto precharge), the READ to bank m will interrupt the READ on bank n, CAS latency later (Figure 14).
11. For a READ without auto precharge interrupted by a WRITE (with or without auto precharge), the WRITE to bank m will interrupt the READ on bank n when registered (Figure 16 and Figure 17). DQM should be used one clock prior to the WRITE command to prevent bus contention.
12. For a WRITE without auto precharge interrupted by a READ (with or without auto precharge), the READ to bank m will interrupt the WRITE on bank n when registered (Figure 24), with the data-out appearing CAS latency later. The last valid WRITE to bank n will be data-in registered one clock prior to the READ to bank m.
13. For a WRITE without auto precharge interrupted by a WRITE (with or without auto precharge), the WRITE to bank will interrupt the WRITE on bank n when registered (Figure 22). The last valid WRITE to bank n will be data-in registered one clock prior to the READ to bank m.
14. For a READ with auto precharge interrupted by a READ (with or without auto precharge), the READ to bank m will interrupt the READ on bank n, CAS latency later. The PRECHARGE to bank n will begin when the READ to bank m is registered (Figure 31).
15. For a READ with auto precharge interrupted by a WRITE (with or without auto precharge), the WRITE to bank m will interrupt the READ on bank n when registered. DQM should be used two clocks prior to the WRITE command to prevent bus contention. The PRECHARGE to bank n will begin when the WRITE to bank m is registered (Figure 32).
16. For a WRITE with auto precharge interrupted by a READ (with or without auto precharge), the READ to bank m will interrupt the WRITE on bank n when registered, with the data-out appearing CAS latency later. The PRECHARGE to bank n will begin after t^1WR is met, where t^1WR begins when the READ to bank m is registered. The last valid WRITE bank n will be data-in registered one clock prior to the READ to bank m (Figure 33).
17. For a WRITE with auto precharge interrupted by a WRITE (with or without auto precharge), the WRITE to bank m will interrupt the WRITE on bank n when registered. The PRECHARGE to bank n will begin after t^1WR is met, where t^1WR begins when the WRITE to bank m is registered. The last valid WRITE to bank n will be data registered one clock to the WRITE to bank m (Figure 34).

Absolute Maximum Ratings

Voltage on VDD/VDDQ Supply
 Relative to Vss(LC devices) -1V to +4.6V
 Relative to Vss(V devices) 0.5V to +3.6V
 Voltage on Inputs, NC or I/O Pins
 Relative to Vss(LC, devices) -1V to +4.6V
 Relative to Vss(V devices) -0.5V to +3.6V
 Operating Temperature
 T_A (Commercial) 0°C to +70°C
 T_A (Industrial) -40°C to +85°C
 T_A (Extended) -25°C to +75°C
 Storage Temperature (plastic) -55°C to +150°C

Stresses greater than those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only, and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

Table 12: DC Electrical Characteristics and Operating Conditions (LC Version)

Notes: 1, 6; notes appear on page 47; VDD = +3.3V ±0.3V, VDDQ = +3.3V ±0.3V

PARAMETER/CONDITION	SYMBOL	MIN	MAX	UNITS	NOTES
Supply Voltage	VDD	3	3.6	V	
I/O Supply Voltage	VDDQ	3	3.6	V	
Input High Voltage: Logic 1; All inputs	V _{IH}	2	VDD + 0.3	V	22
Input Low Voltage: Logic 0; All inputs	V _{IL}	-0.3	0.8	V	22
Data Output High Voltage: Logic 1; All inputs	V _{OH}	2.4	–	V	
Data Output LOW Voltage: Logic 0; All inputs	V _{OL}	–	0.4	V	
Input Leakage Current: Any Input 0V ≤ VIN ≤ VDD (All other pins not under test = 0V)	I _I	-5	5	μA	
Output Leakage Current: DQs are disabled; 0V ≤ VOUT ≤ VDDQ	I _{OZ}	-5	5	μA	

Table 13: DC Electrical Characteristics and Operating Conditions (V Version)

Notes: 1, 6; notes appear on page 47; VDD = 2.5 ±0.2V, VDDQ = +2.5V ±0.2V or +1.8V ±0.15V

PARAMETER/CONDITION	SYMBOL	MIN	MAX	UNITS	NOTES
Supply Voltage	VDD	2.3	2.7	V	
I/O Supply Voltage	VDDQ	1.65	2.7	V	
Input High Voltage: Logic 1; All inputs	V _{IH} (DQ)	1.25	VDDQ + 0.3	V	22
	V _{IH} (non-DQ)	1.25	VDD + 0.3		
Input Low Voltage: Logic 0; All inputs	V _{IL}	-0.3	+0.55	V	22
Data Output High Voltage: Logic 1; All inputs	V _{OH}	VDDQ - 0.2	–	V	
Data Output Low Voltage: Logic 0; All inputs	V _{OL}	–	0.2	V	
Input Leakage Current: Any input 0V ≤ VIN ≤ VDD (All other pins not under test = 0V)	I _I	-5	5	μA	
Output Leakage Current: DQs are disabled; 0V ≤ VOUT ≤ VDDQ	I _{OZ}	-5	5	μA	

Table 14: Electrical Characteristics and Recommended AC Operating Conditions

Notes: 5, 6, 7, 8, 9, 11; notes appear on page 47

AC CHARACTERISTICS PARAMETER		SYMBOL	-75M		-8		-10		UNITS	NOTES
			MIN	MAX	MIN	MAX	MIN	MAX		
Access time from CLK (positive. edge)	CL = 3	$t_{AC}^{(3)}$		5.4		7		7	ns	
	CL = 2	$t_{AC}^{(2)}$		6		8		8	ns	
	CL = 1	$t_{AC}^{(1)}$		na		19		22	ns	
Address hold time		t_{AH}	0.8		1		1		ns	
Address setup time		t_{AS}	1.5		2.5		2.5		ns	
CLK high-level width		t_{CH}	3		3		3		ns	
CLK low-level width		t_{CL}	2.5		3		3		ns	
Clock cycle time	CL = 3	$t_{CK}^{(3)}$	7.5		8		10		ns	23
	CL = 2	$t_{CK}^{(2)}$	9.6		9.6		12		ns	23
	CL = 1	$t_{CK}^{(1)}$	n/a		20		25		ns	23
CKE hold time		t_{CKH}	1		1		1		ns	
CKE setup time		t_{CKS}	2.5		2.5		2.5		ns	
CS#, RAS#, CAS#, WE#, DQM hold time		t_{CMH}	0.8		1		1		ns	
CS#, RAS#, CAS#, WE#, DQM setup time		t_{CMS}	1.5		2.5		2.5		ns	
Data-in hold time		t_{DH}	0.8		1		1		ns	
Data-in setup time		t_{DS}	1.5		2.5		2.5		ns	
Data-out high-impedance time	CL = 3	$t_{HZ}^{(3)}$		5.4		7		7	ns	10
	CL = 2	$t_{HZ}^{(2)}$		6		8		8	ns	10
	CL = 1	$t_{HZ}^{(1)}$		na		19		22	ns	10
Data-out low-impedance time		t_{LZ}	1		1		1		ns	
Data-out hold time (load)		t_{OH}	2.5		2.5		2.5		ns	27
Data-out hold time (no load)		t_{OHn}	1.8		1.8		1.8		ns	
ACTIVE to PRECHARGE command		t_{RAS}	44	120,000	48	120,000	50	120,000	ns	
ACTIVE to ACTIVE command period		t_{RC}	66		80		100		ns	
ACTIVE to READ or WRITE delay		t_{RCD}	19		20		20		ns	
Refresh period (4,096 rows)		t_{REF}		64		64		64	ms	
AUTO REFRESH command period		t_{RFC}	66		80		100		ns	
PRECHARGE command period		t_{RP}	19		20		20		ns	
ACTIVE bank a to ACTIVE bank b command		t_{RRD}	2		2		2		t_{CK}	
Transition time		t_T	0.3	1.2	0.5	1.2	0.5	1.2	ns	7
WRITE recovery time Auto Precharge Mode Manual Precharge Mode		$t_{WR}^{(a)}$	1 CLK +7.5ns		1 CLK +7ns		1 CLK +5ns		-	24
		$t_{WR}^{(m)}$	15		15		15		ns	25
Exit SELF REFRESH to ACTIVE command		t_{XSR}	67		80		100		ns	20

Table 15: AC Functional Characteristics

Notes: 5, 6, 7, 8, 9, 11; notes appear on page 47

PARAMETER	SYMBOL	-75M	-8	-10	UNITS	NOTES
READ/WRITE command to READ/WRITE command	t_{CCD}	1	1	1	t_{CK}	17
CKE to clock disable or power-down entry mode	t_{CKED}	1	1	1	t_{CK}	14
CKE to clock enable or power-down exit setup mode	t_{PED}	1	1	1	t_{CK}	14
DQM to input data delay	t_{DQD}	0	0	0	t_{CK}	17
DQM to data mask during WRITES	t_{DQM}	0	0	0	t_{CK}	17
DQM to data high-impedance during READS	t_{DQZ}	2	2	2	t_{CK}	17
WRITE command to input data delay	t_{DWD}	0	0	0	t_{CK}	17
Data-in to ACTIVE command	t_{DAL}	5	5	5	t_{CK}	15, 21
Data-in to PRECHARGE command	t_{DPL}	2	2	2	t_{CK}	16, 21
Last data-in to burst STOP command	t_{BDL}	1	1	1	t_{CK}	17
Last data-in to new READ/WRITE command	t_{CDL}	1	1	1	t_{CK}	17
Last data-in to PRECHARGE command	t_{RDL}	2	2	2	t_{CK}	16, 21
LOAD MODE REGISTER command to ACTIVE or REFRESH command	t_{MRD}	2	2	2	t_{CK}	26
Data-out to high-impedance from PRECHARGE command	CL = 3 $t_{ROH(3)}$	3	3	3	t_{CK}	17
	CL = 2 $t_{ROH(2)}$	2	2	2	t_{CK}	17
	CL = 1 $t_{ROH(1)}$		1	1	t_{CK}	17

Table 16: IDD Specifications and Conditions (x16)

Notes: 1, 3, 6, 11, 13, 31 ; notes appear on page 47; VDD = VDDQ = +3.3V ±0.3V or VDD = VDDQ = 2.5V ±0.2V or VDD = +2.5V ±0.2V, VDDQ = +1.8V ±0.15V

PARAMETER/CONDITION	SYMBOL	MAX			UNITS	NOTES
		-75M	-8	-10		
Operating Current: Active Mode; Burst = 2; READ or WRITE; $t_{RC} = t_{RC}(\text{MIN})$	IDD1	130	130	100	mA	18, 19
Standby Current: Power-Down Mode; All banks idle; CKE = LOW	IDD2	450	450	450	µA	12, 33
Standby Current: Active Mode; CKE = HIGH; CS# = HIGH; All banks active after t_{RCD} met; No accesses in progress	IDD3	40	40	35	mA	19
Operating Current: Burst Mode; Page burst; READ or WRITE; All banks active	IDD4	115	100	95	mA	18, 19
Auto Refresh Current CKE = HIGH; CS# = HIGH	$t_{RFC} = t_{RFC}(\text{MIN})$	225	210	170	mA	12, 18, 19, 32, 33
	$t_{RFC} = 15.625\mu\text{s}$	3	3	3	mA	

Table 17: IDD7 Self Refresh Current Options (x16)

Notes: 4 appears on page 47; VDD = VDDQ = +3.3V ±0.3V or VDD = VDDQ = 2.5V ±0.2V or VDD = +2.5V ±0.2V, VDDQ = +1.8V ±0.15V

TEMPERATURE COMPENSATED SELF REFRESH (TCSR)			
PARAMETER/CONDITION	MAX TEMPERATURE	-75M, -8, -10	UNITS
Self Refresh Current: CKE < 0.2V (E4 = 1, E3=1)	85°C	800	µA
Self Refresh Current: CKE < 0.2V (E4 = 0, E3=0)	70°C	500	µA
Self Refresh Current: CKE < 0.2V (E4 = 0, E3=1)	45°C	350	µA
Self Refresh Current: CKE < 0.2V (E4 = 1, E3=0)	15°C	300	µA

Table 18: IDD Specifications And Conditions (x32)

Notes: 1, 3, 6, 11, 13, 31 ; notes appear on page 47; VDD = VDDQ = +3.3V ±0.3V or VDD = VDDQ = 2.5V ±0.2V or VDD = +2.5V ±0.2V, VDDQ = +1.8V ±0.15V

PARAMETER/CONDITION	SYMBOL	MAX			UNITS	NOTES	
		-75M	-8	-10			
Operating Current: Active Mode; Burst = 2; READ or WRITE; $t_{RC} = t_{RC}(\text{MIN})$	IDD1	150	150	120	mA	18, 19	
Standby Current: Power-Down Mode; All banks idle; CKE = LOW	IDD2	450	450	450	μA	12, 33	
Standby Current: Active Mode; CKE = HIGH; CS# = HIGH; All banks active after t_{RCD} met; No accesses in progress	IDD3	45	45	40	mA	19	
Operating Current: Burst Mode; Page burst; READ or WRITE; All banks active	IDD4	130	115	110	mA	18, 19	
Auto Refresh Current CKE = HIGH; CS# = HIGH	$t_{RFC} = t_{RFC}(\text{MIN})$	IDD5	235	220	180	mA	12, 18, 19, 32, 33
	$t_{RFC} = 15.625\mu\text{s}$	IDD6	3	3	3	mA	

Table 19: IDD7 Self Refresh Current Options (x32)

Notes: 4 appears on page 47; VDD = VDDQ = +3.3V ±0.3V or VDD = VDDQ = 2.5V ±0.2V or VDD = +2.5V ±0.2V, VDDQ = +1.8V ±0.15V

TEMPERATURE COMPENSATED SELF REFRESH (TCSR)			
PARAMETER/CONDITION	MAX TEMPERATURE	-75M, -8, -10	UNITS
Self Refresh Current: CKE < 0.2V (E4 = 1, E3=1)	85°C	1000	μA
Self Refresh Current: CKE < 0.2V (E4 = 0, E3=0)	70°C	550	μA
Self Refresh Current: CKE < 0.2V (E4 = 0, E3=1)	45°C	400	μA
Self Refresh Current: CKE < 0.2V (E4 = 1, E3=0)	15°C	350	μA

Table 20: Capacitance (FBGA Package)

(Note: 2 notes appear on page 47)

PARAMETER	SYMBOL	MIN	MAX	UNITS	NOTES
Input Capacitance: CLK	C11	1.5	3.5	pF	28
Input Capacitance: All other input-only pins	C12	1.5	3.8	pF	29
Input/Output Capacitance: DQs	C10	3.0	6.0	pF	30

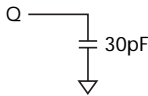
Table 21: Capacitance (TSOP Package)

(Note: 2 notes appear on page 47)

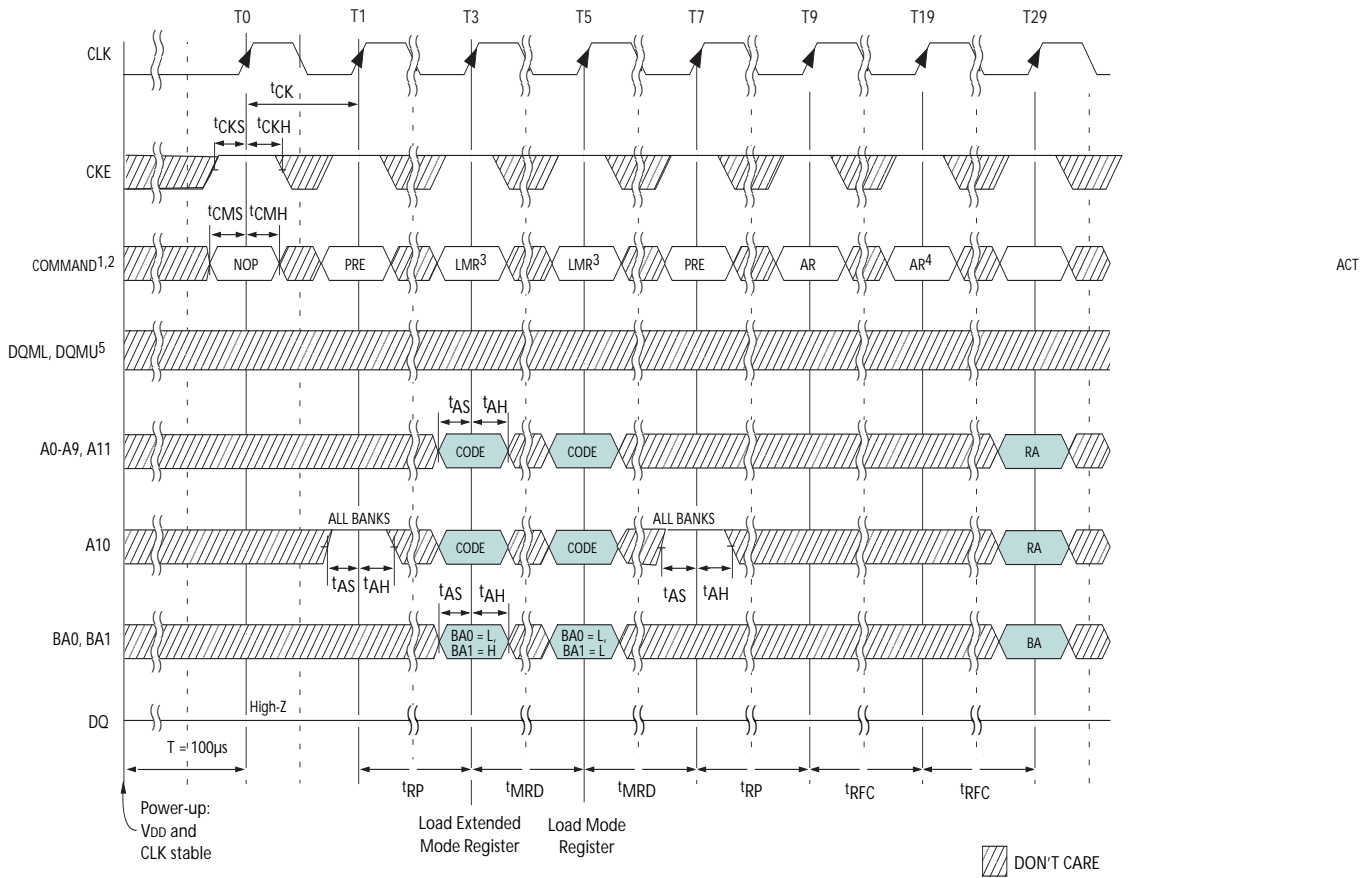
PARAMETER	SYMBOL	MIN	MAX	UNITS	NOTES
Input Capacitance: CLK	C11	2.5	3.5	pF	28
Input Capacitance: All other input-only pins	C12	2.5	3.8	pF	29
Input/Output Capacitance: DQs	C10	4.0	6.0	pF	30

Notes

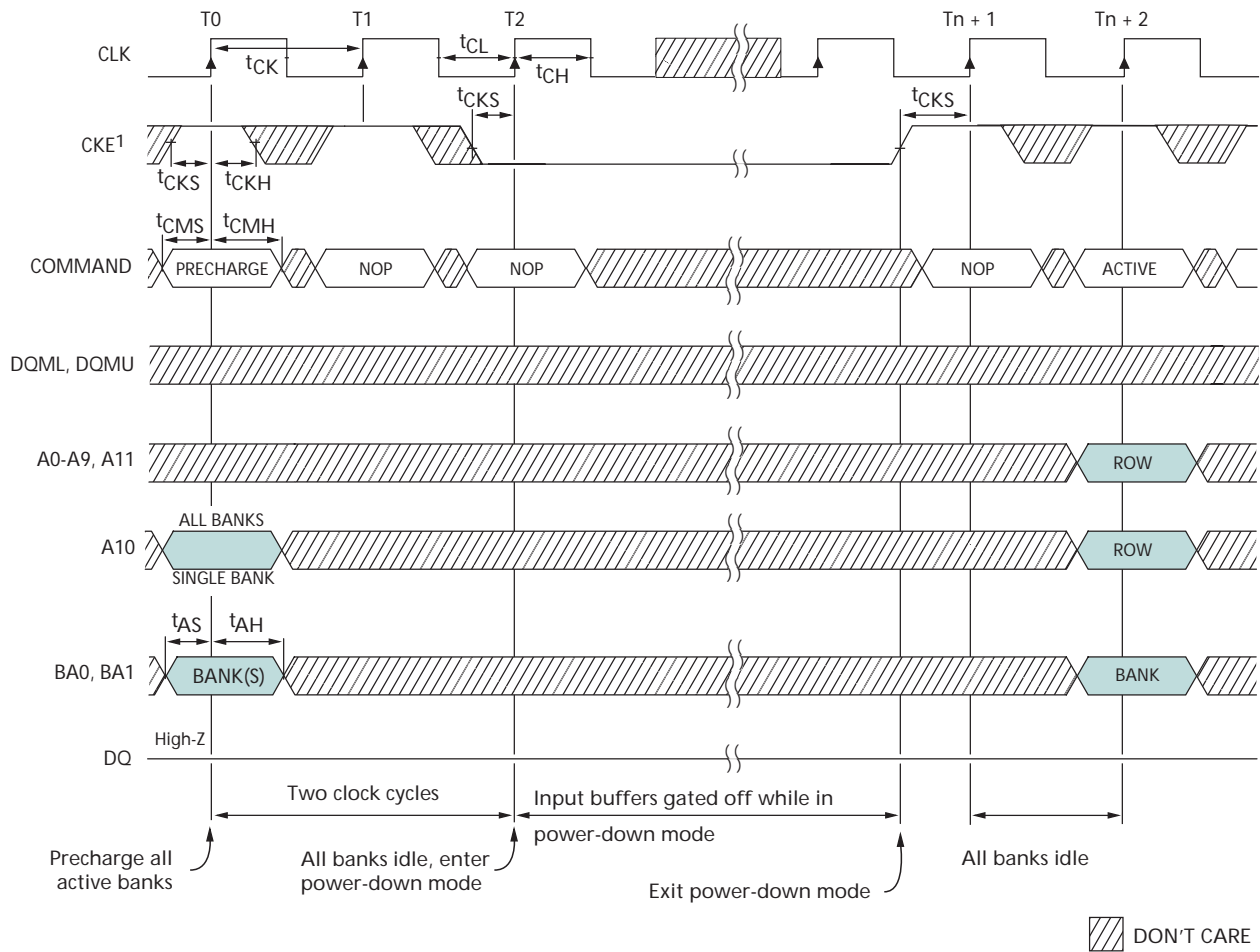
1. All voltages are referenced to Vss
2. This parameter is sampled. VDD, VDDQ = +3.3V; T_A = 25°C; pin under test biased at 1.4V, f = 1 MHz,
3. I_{DD} is dependent on output loading and cycle rates. Specified values are obtained with minimum cycle time and the outputs open.
4. Enables on-chip refresh and address counters.
5. The minimum specifications are used only to indicate cycle time at which proper operation over the full operational temperature range is ensured (T_A = Commercial, IT or XT).
6. An initial pause of 100μs is required after power-up, followed by two AUTO REFRESH commands, before proper device operation is ensured. (VDD and VDDQ must be powered up simultaneously. VSS and VSSQ must be at same potential.) The two AUTO REFRESH command wake-ups should be repeated any time the t^{REF} refresh requirement is exceeded.
7. AC characteristics assume t^T = 1ns.
8. In addition to meeting the transition rate specification, the clock and CKE must transit between V_{IH} and V_L (or between V_L and V_{IH}) in a monotonic manner.
9. Outputs measured at 1.5V (for LC devices) or at 1.25V (V devices) with equivalent load:



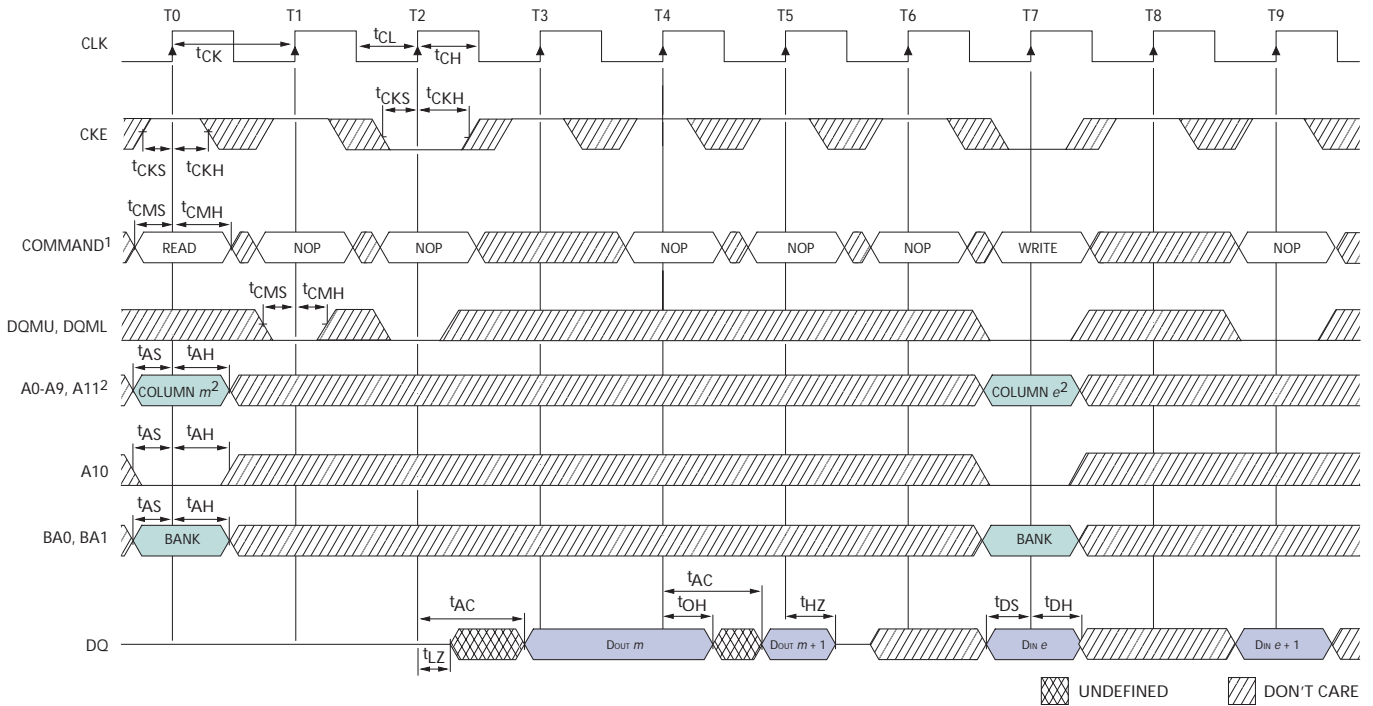
A circuit diagram showing an output pin labeled 'Q' connected to a 30pF capacitor, which is then connected to ground. The capacitor is represented by two parallel lines of unequal length, with the longer line on the right.
10. t^{HZ} defines the time at which the output achieves the open circuit condition; it is not a reference to V_{OH} or V_{OL}. The last valid data element will meet t^{OH} before going High-Z.
11. AC timing and I_{DD} tests use established values for V_L and V_{IH}, with timing referenced to V_{IH}/2 crossover point. If the input transition time is longer than 1ns, then the timing is referenced at V_L(MAX) and V_{IH}(MIN) and no longer at the V_{IH}/2 crossover point. Established tester values follow: V_L = 0V, V_{IH} = 3.0V for LC devices, and V_{IH} = 2.3V for V devices.
12. Other input signals are allowed to transition no more than once every two clocks and are otherwise at valid V_{IH} or V_L levels.
13. I_{DD} specifications are tested after the device is properly initialized.
14. Timing actually specified by t^{CKS}; clock(s) specified as a reference only at minimum cycle rate.
15. Timing actually specified by t^{WR} plus t^{RP}; clock(s) specified as a reference only at minimum cycle rate.
16. Timing actually specified by t^{WR}.
17. Required clocks are specified by JEDEC functionality and are not dependent on any timing parameter.
18. The I_{DD} current will increase or decrease proportionally according to the amount of frequency alteration for the test condition.
19. Address transitions average one transition every two clocks.
20. CLK must be toggled a minimum of two times during this period.
21. Based on t^{CK} = 125MHz for -8 and t^{CK} = 100MHz for -10.
22. V_{IH} overshoot: V_{IH} (MAX) = VDDQ + 2V for a pulse width ≤ 3ns, and the pulse width cannot be greater than one third of the cycle rate. V_L undershoot: V_L (MIN) = -2V for a pulse width ≤ 3ns and can not be greater than one third of the cycle rate.
23. The clock frequency must remain constant (stable clock is defined as a signal cycling within timing constraints specified for the clock pin) during access or precharge states (READ, WRITE, including t^{WR}, and PRECHARGE commands). CKE may be used to reduce the data rate.
24. Auto precharge mode only. The precharge timing budget (t^{RP}) begins at 5.4ns for -8 after the first clock delay, after the last WRITE is executed.
25. Manual Precharge mode only.
26. JEDEC and PC100 specify three clocks.
27. Parameter guaranteed by design.
28. PC100 specifies a maximum of 4pF
29. PC100 specifies a maximum of 5pF
30. PC100 specifies a maximum of 6.5pF
31. For -75M, CL=3 and t^{CK} = 7.5ns; For -8, CL = 3 and t^{CK} = 8ns; for -10, CL = 3 and t^{CK} = 10ns.
32. CKE is HIGH during refresh command period t^{RFC} (MIN) else CKE is LOW. The I_{DD6} limit is actually a nominal value and does not result in a fail value.
33. Specified with I/Os in steady state condition.

Figure 35: Initialize and Load Mode Register

NOTE:

1. The two AUTO REFRESH commands at T9 and T19 may be applied before either LOAD MODE REGISTER (LMR) command.
2. PRE = PRECHARGE command, LMR = LOAD MODE REGISTER command, AR = AUTO REFRESH command, ACT = ACTIVE command, RA = Row Address, BA = Bank Address
3. The Load Mode Register for both MR/EMR and 2 Auto Refresh commands can be in any order. However, all must occur prior to an Active command
4. Optional refresh command.
5. Although not required, to prevent bus contention it is suggested to keep DQM high during the Initialization sequence. See Table 14, Electrical Characteristics and Recommended AC Operating Conditions, on page 43

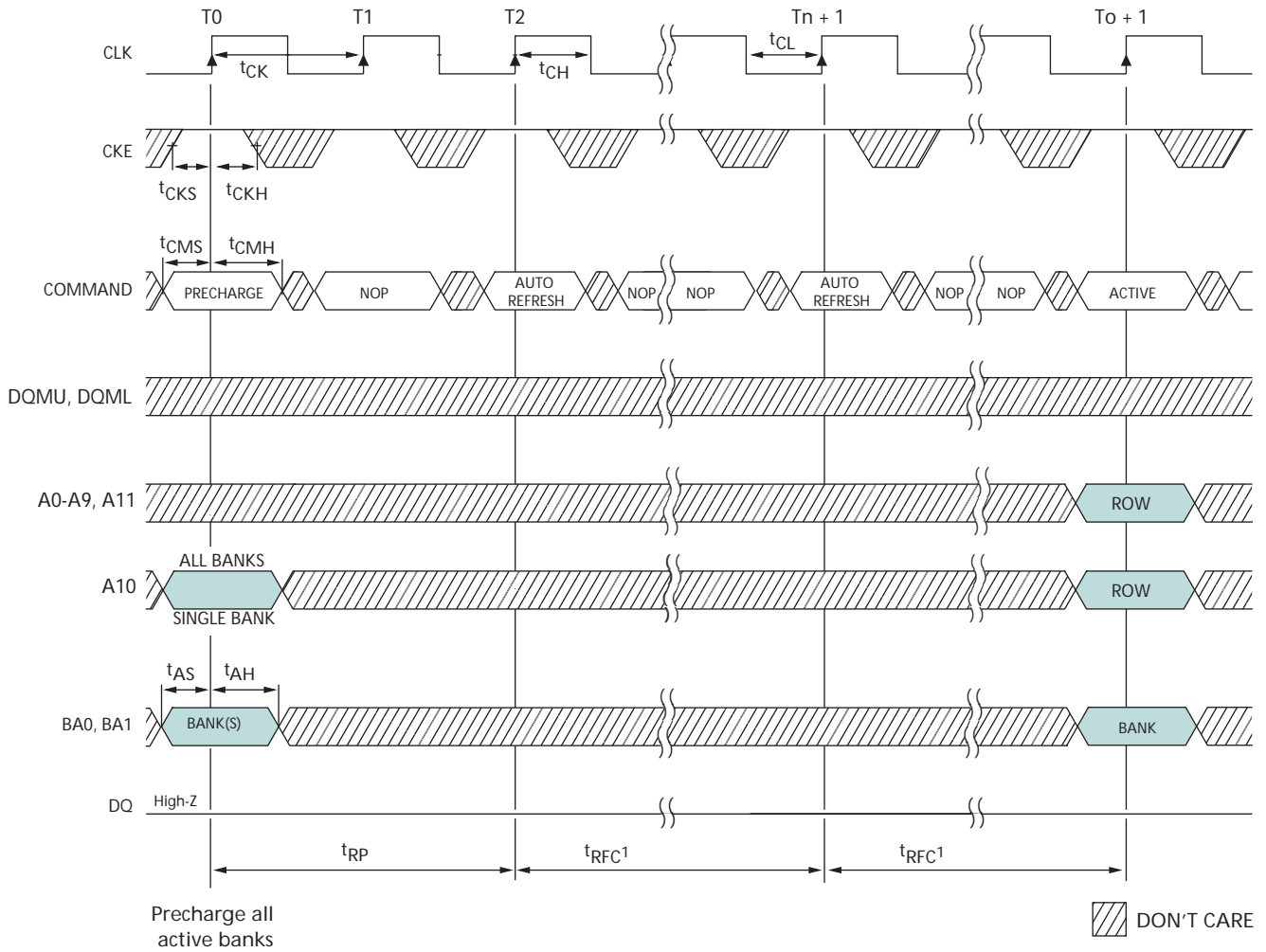
Figure 36: Power-down Mode

NOTE:

1. Violating refresh requirements during power-down may result in a loss of data.
See Table 14, Electrical Characteristics and Recommended AC Operating Conditions, on page 43

Figure 37: Clock Suspend Mode

NOTE:

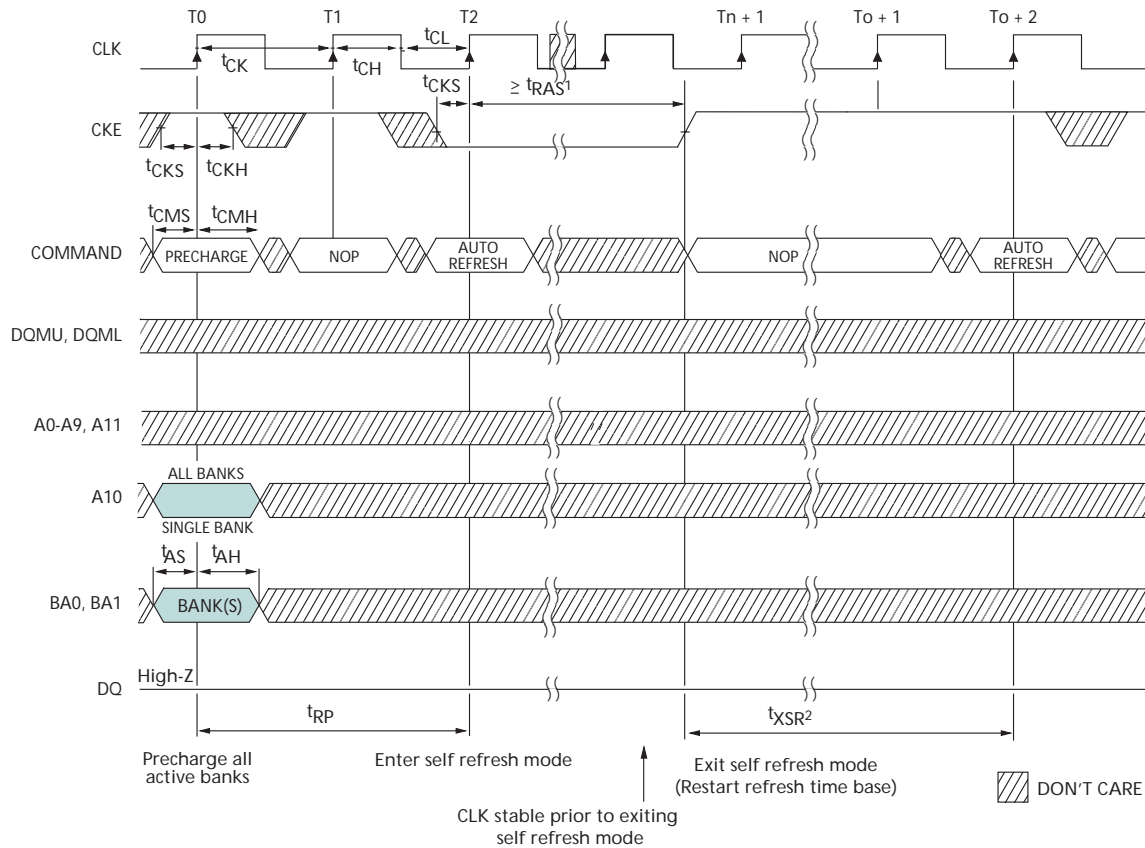
1. For this example, the burst length = 2, the CAS latency = 3, and auto precharge is disabled.
2. x16:A9 and A11 = "Don't Care"
x32:A8, A9 and A11 = "Don't Care"
See Table 14, Electrical Characteristics and Recommended AC Operating Conditions, on page 43

Figure 38: Auto Refresh Mode



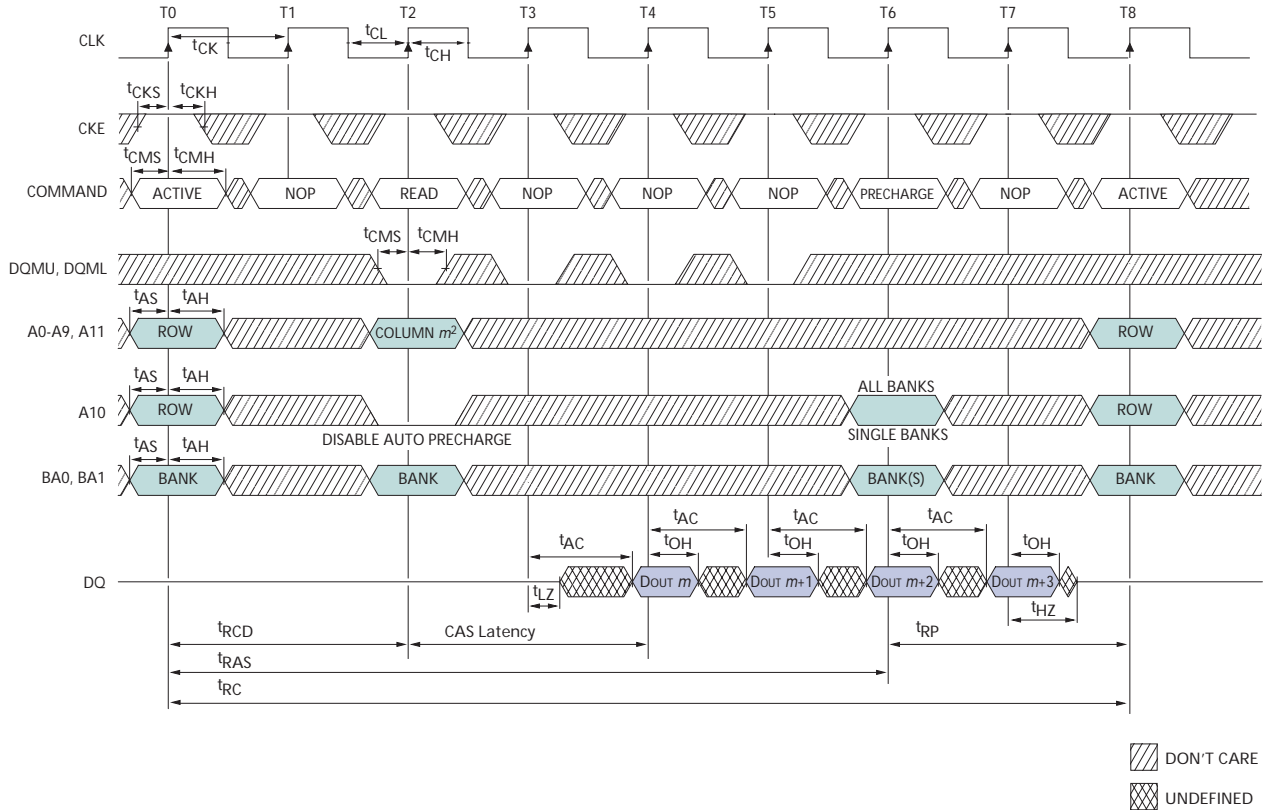
NOTE:

1. Each AUTO REFRESH command performs a refresh cycle. Back-to-back commands are not required. See Table 14, Electrical Characteristics and Recommended AC Operating Conditions, on page 43

Figure 39: Self Refresh Mode

NOTE:

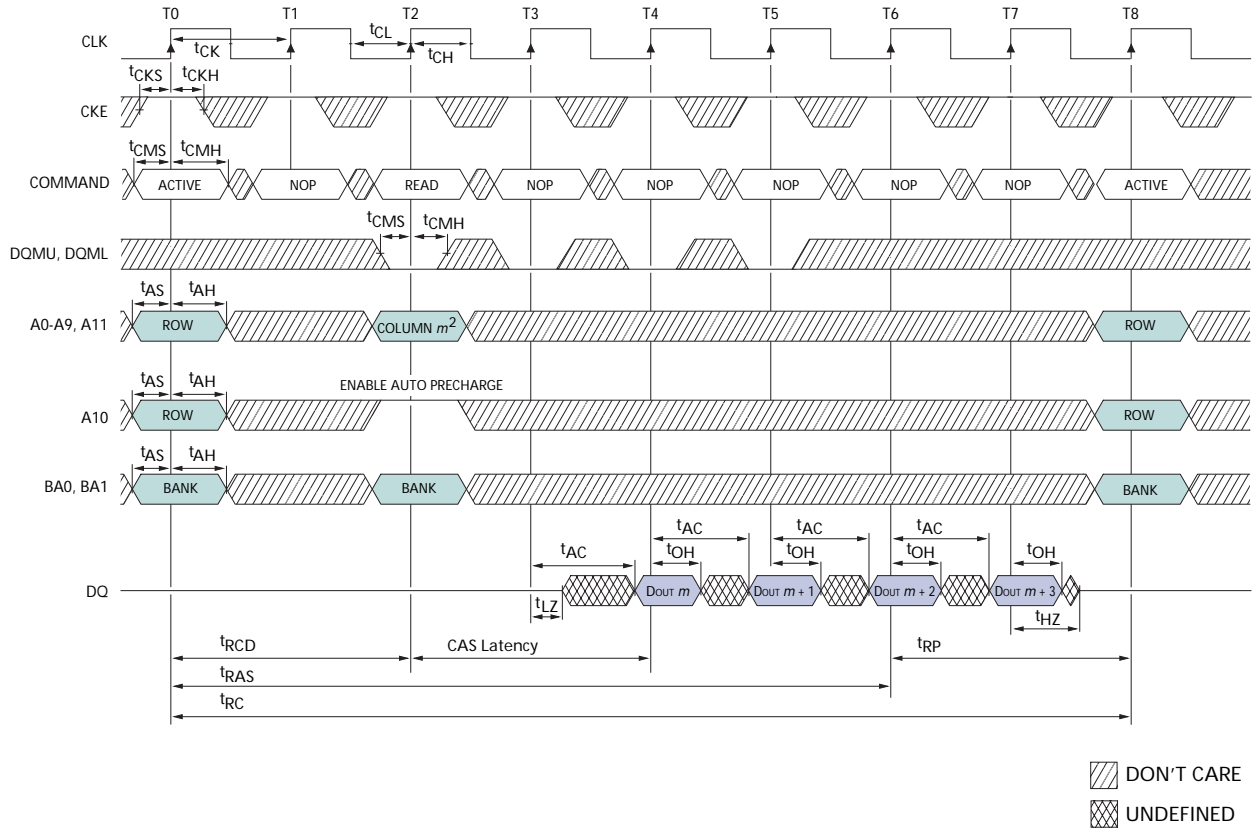
1. No maximum time limit for Self Refresh. $t_{RAS}^{(MAX)}$ only applies to non-Self Refresh mode.
2. t_{XSR} requires a minimum of two clocks regardless of frequency or timing.
3. As a general rule, any time Self Refresh is exited, the DRAM may not re-enter the Self Refresh Mode until all rows have been refreshed via the Auto Refresh command at the distributed refresh rate, ($t_{REF} / \text{number of rows}$), or faster. However, the following exception is allowed. Self Refresh Mode may be re-entered any time after exiting, if the following conditions are all met:
 - a.) The DRAM has been in the Self Refresh Mode for a minimum of 64ms prior to exiting.
 - b.) t_{XSR} has not been violated.
 - c.) At least two Auto Refresh commands are performed during each 15.625us interval while the DRAM remains out of the Self Refresh mode.

See Table 14, Electrical Characteristics and Recommended AC Operating Conditions, on page 43

Figure 40: READ - Without Auto Precharge

NOTE:

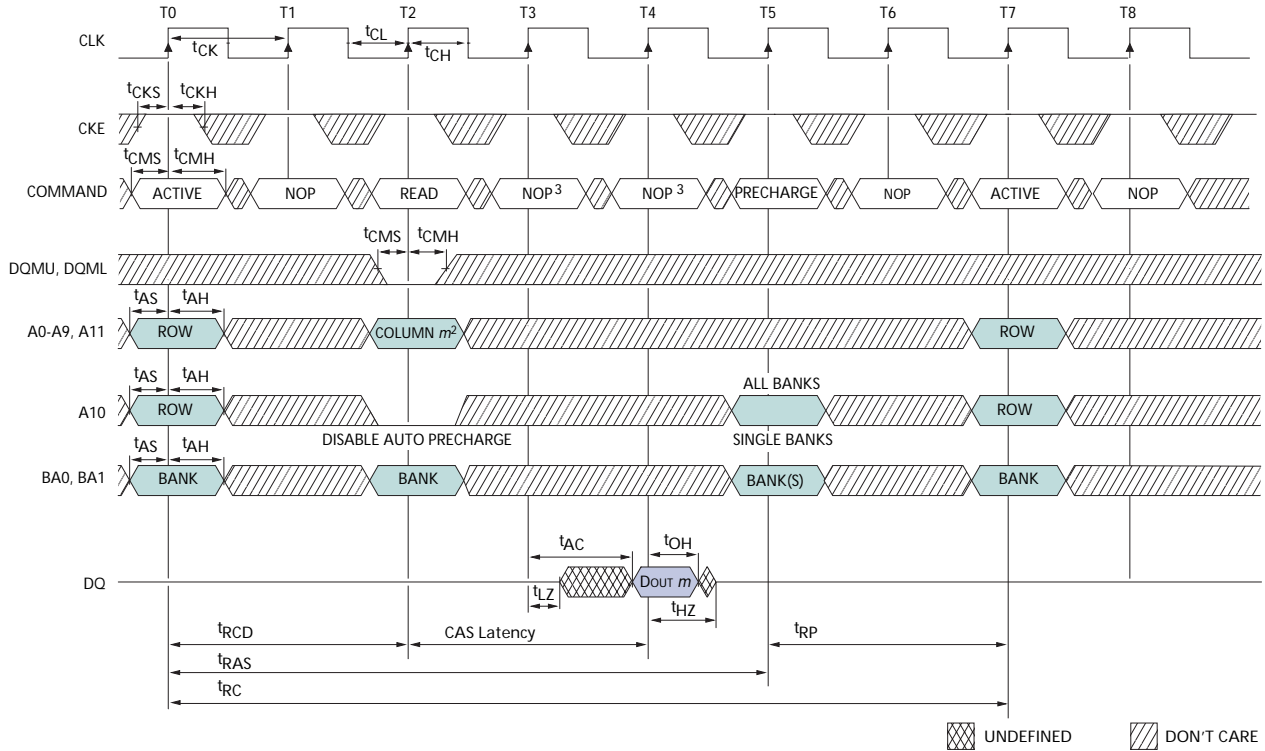
1. For this example, the burst length = 4, the CAS latency = 2, and the READ burst is followed by a "manual" PRECHARGE.
2. x16:A9 and A11 = "Don't Care"
x32:A8, A9, and A11 = "Don't Care"
See Table 14, Electrical Characteristics and Recommended AC Operating Conditions, on page 43

Figure 41: Read – With Auto Precharge

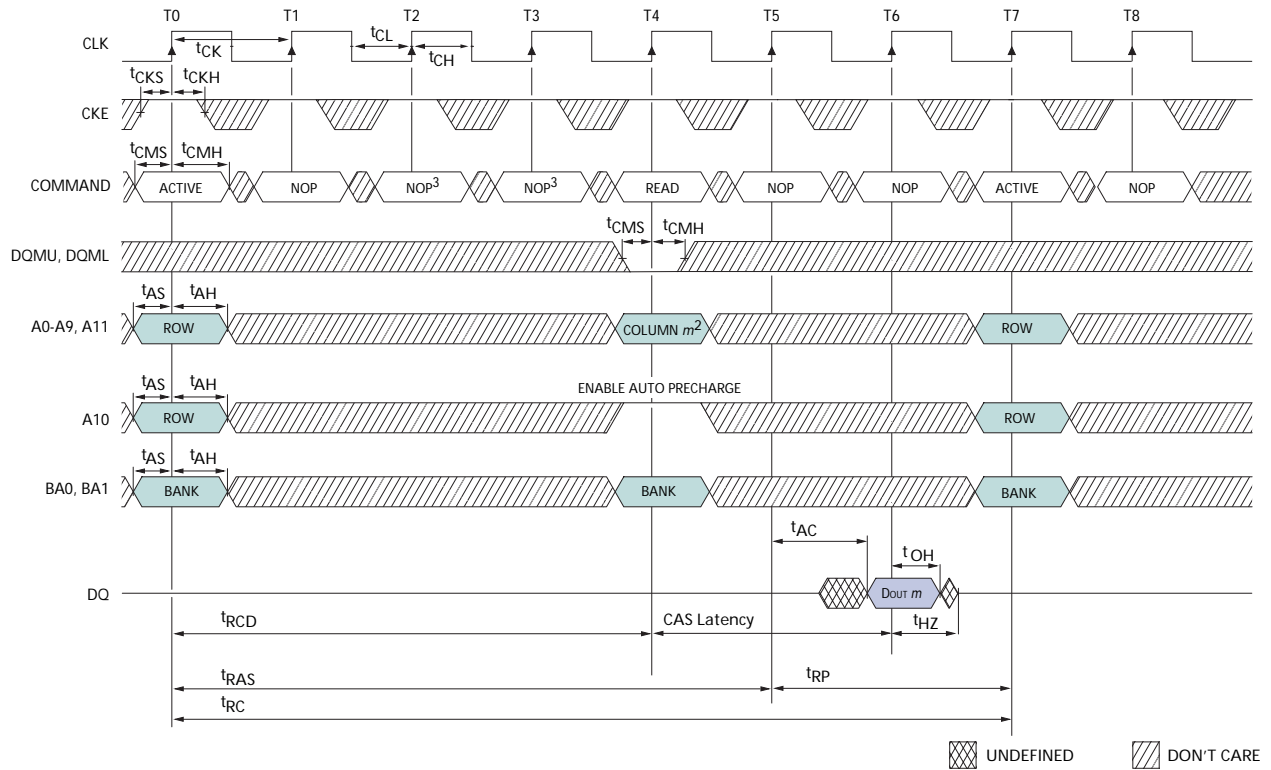


NOTE:

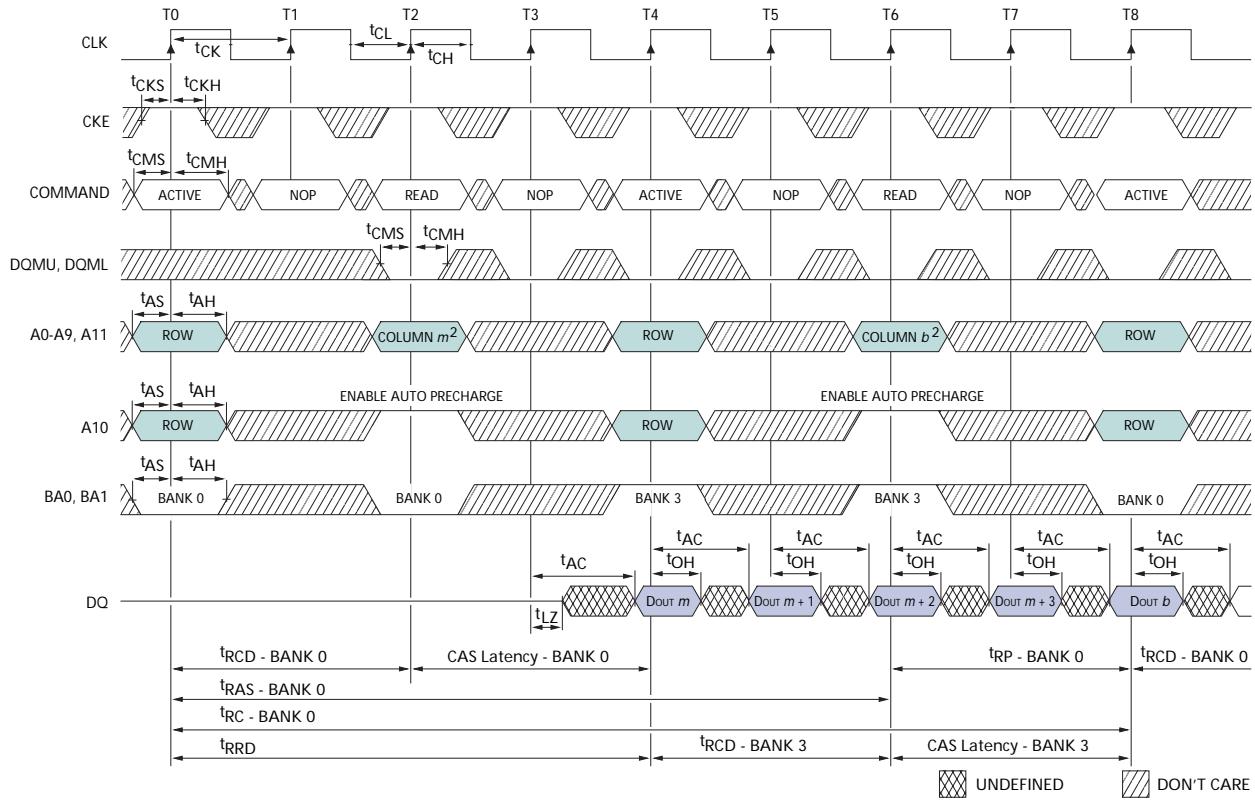
1. For this example, the burst length = 4, the CAS latency = 2.
2. x16:A9 and A11 = "Don't Care"
 x32:A8, A9, and A11 = "Don't Care"
 See Table 14, Electrical Characteristics and Recommended AC Operating Conditions, on page 43

Figure 42: Single Read – Without Auto Precharge

NOTE:

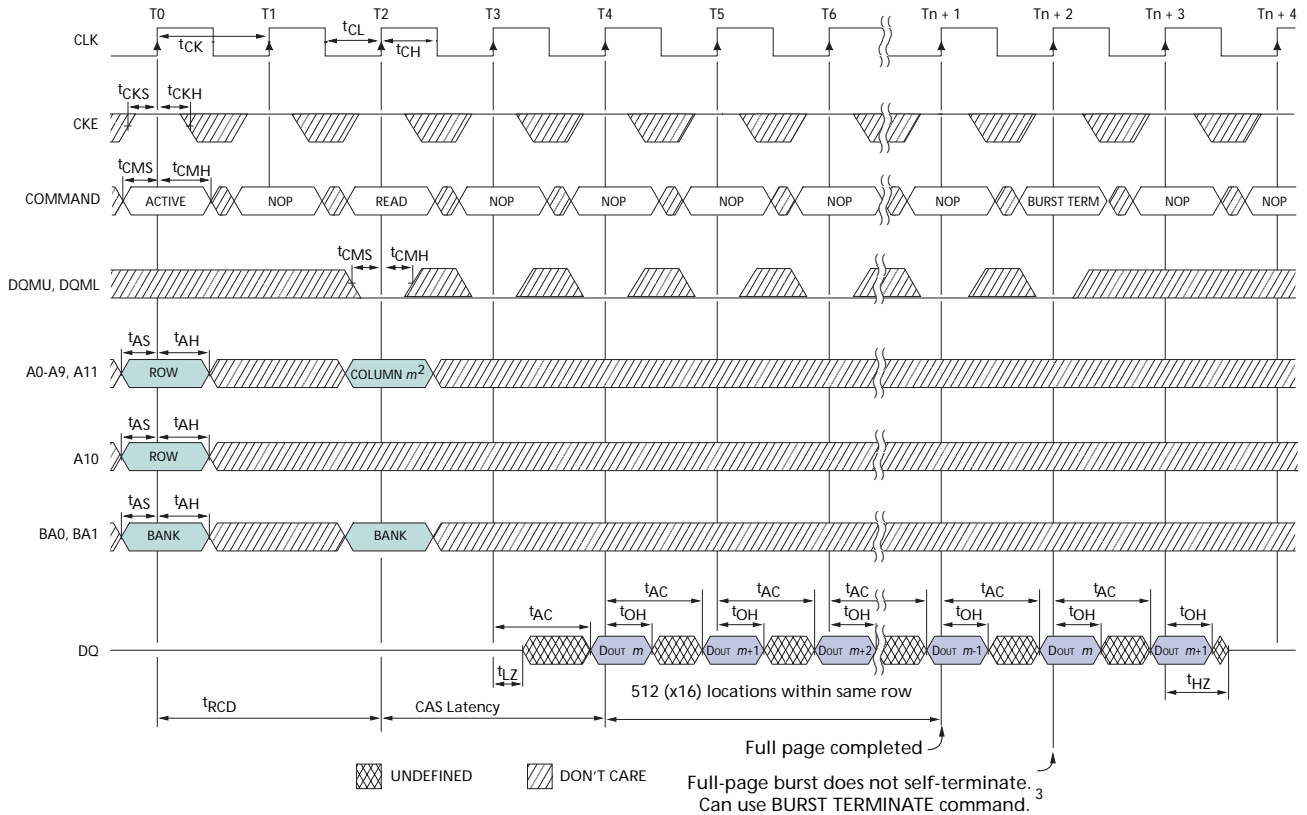
1. For this example, the burst length = 4, the CAS latency = 2, and the READ burst is followed by a “manual” PRECHARGE.
2. x16:A9 and A11 = “Don’t Care”
x32:A8, A9, and A11 = “Don’t Care”
3. PRECHARGE command not allowed or t_{RAS} would be violated.
See Table 14, Electrical Characteristics and Recommended AC Operating Conditions, on page 43

Figure 43: Single Read – With Auto Precharge

NOTE:

1. For this example, the burst length = 4, the CAS latency = 2, and the READ burst is followed by a "manual" PRECHARGE.
2. x16:A9 and A11 = "Don't Care"
x32:A8, A9, and A11 = "Don't Care"
3. PRECHARGE command not allowed or t_{RAS} would be violated.
See Table 14, Electrical Characteristics and Recommended AC Operating Conditions, on page 43

Figure 44: Alternating Bank Read Accesses

NOTE:

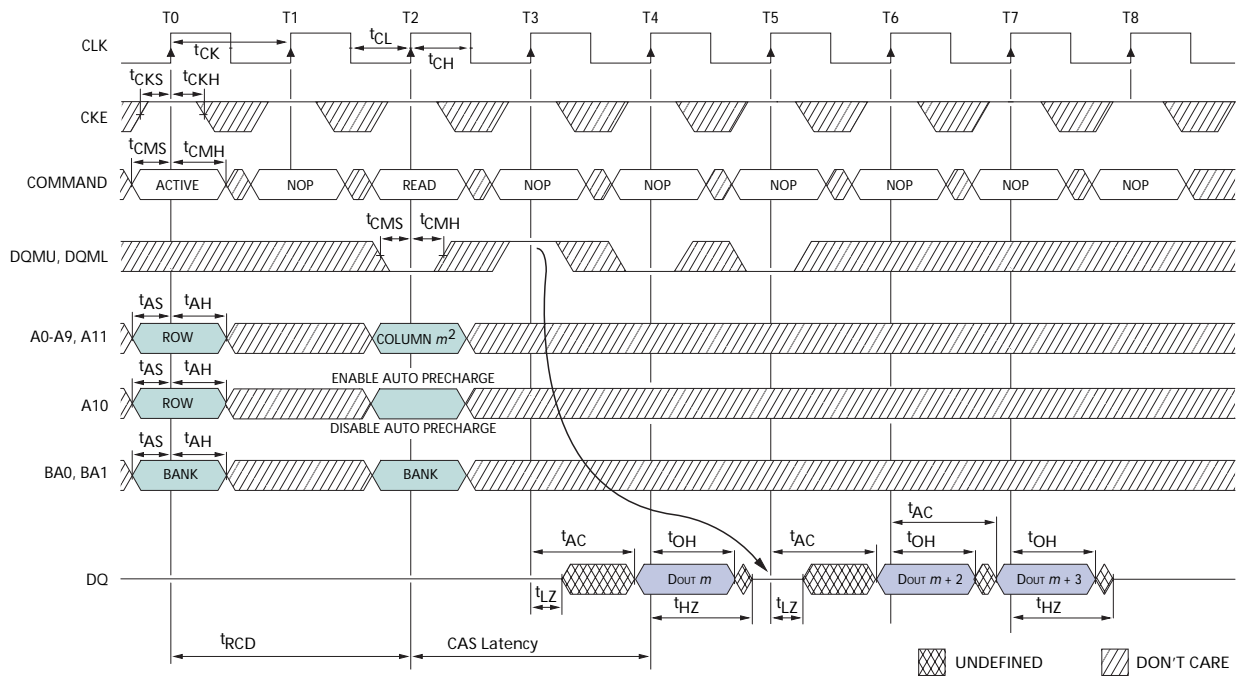
1. For this example, the burst length = 4, the CAS latency = 2.
2. x16:A9 and A11 = "Don't Care"
x32:A8, A9, and A11 = "Don't Care."
See Table 14, Electrical Characteristics and Recommended AC Operating Conditions, on page 43

Figure 45: Read – Full-page Burst

NOTE:

1. For this example, the CAS latency = 2.
2. x16:A9 and A11 = "Don't Care"
x32:A8, A9, and A11 = "Don't Care"
3. Page left open; no ^tRP.

See Table 14, Electrical Characteristics and Recommended AC Operating Conditions, on page 43

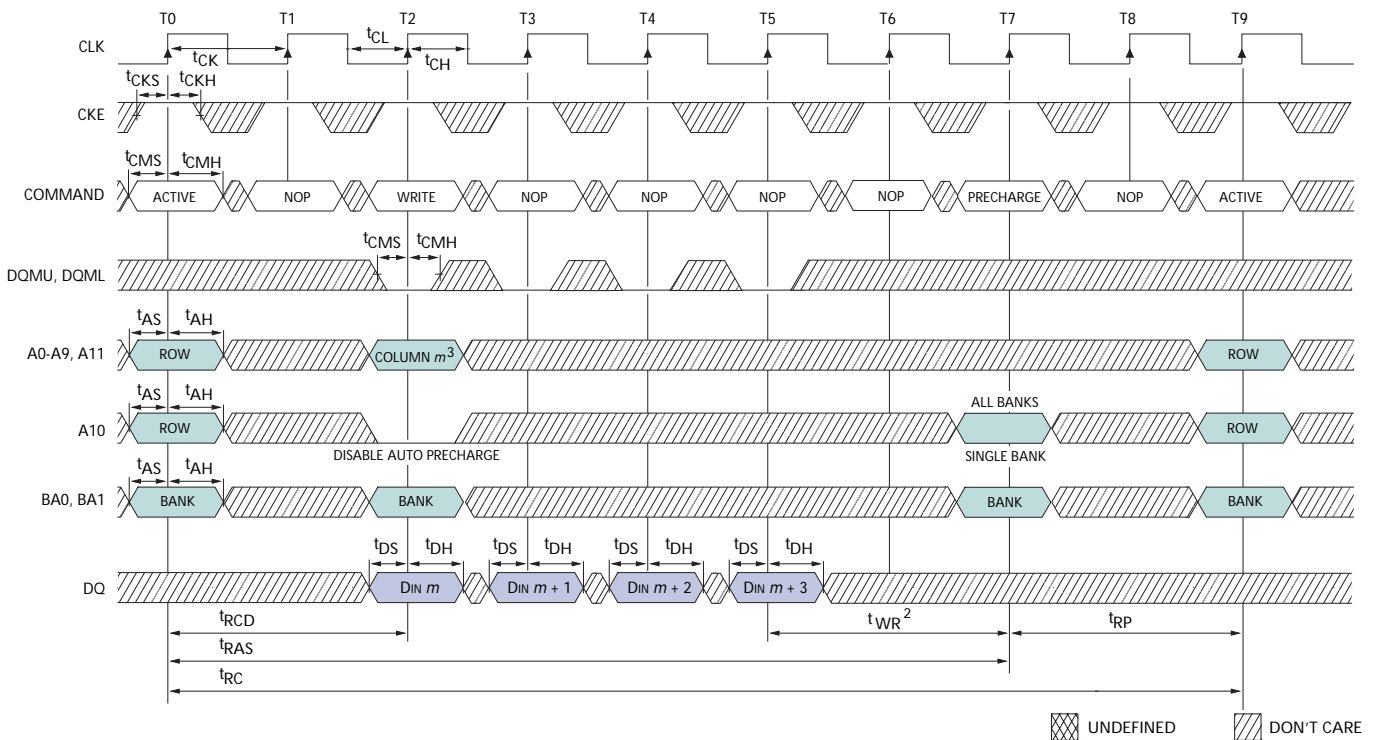
Figure 46: Read – DQM Operation



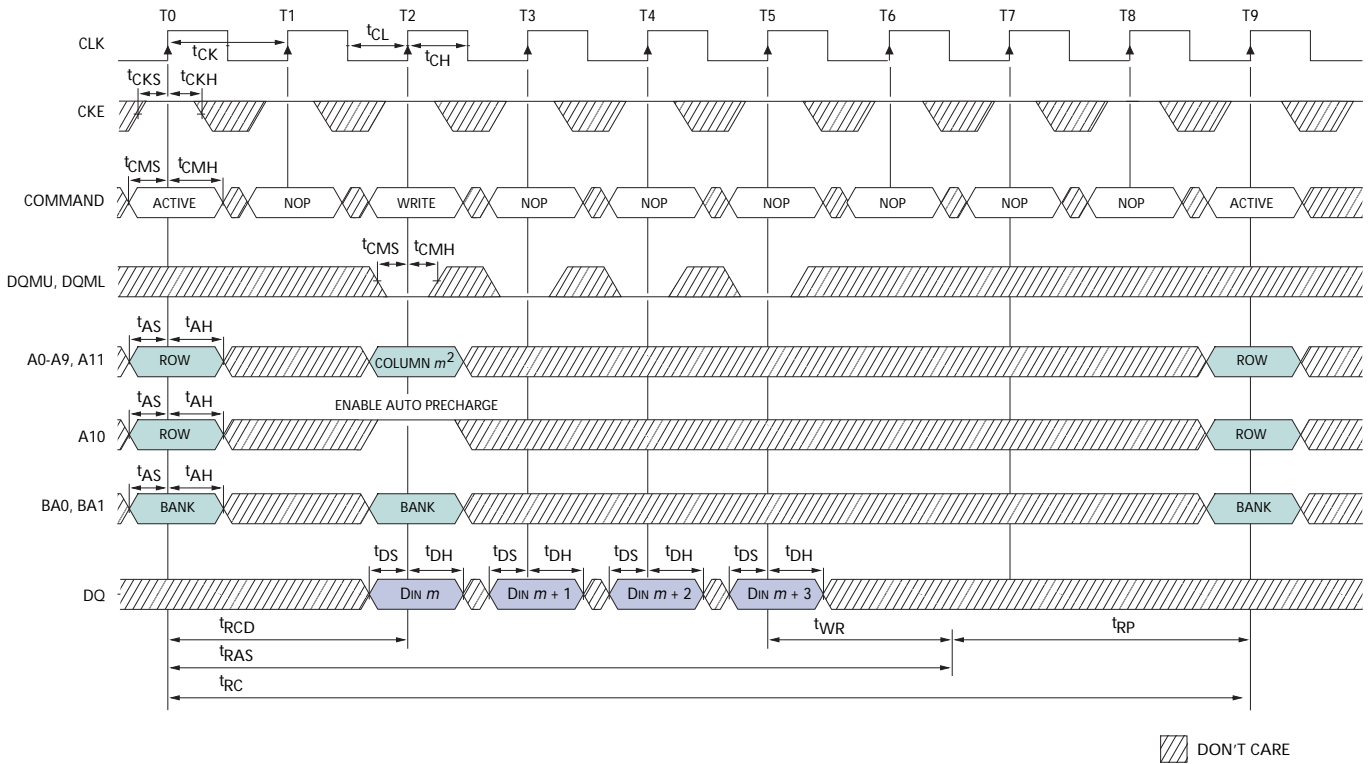
NOTE:

1. For this example, the CAS latency = 2.
2. x16:A9 and A11 = "Don't Care"
x32:A8, A9, and A11 = "Don't Care"

See Table 14, Electrical Characteristics and Recommended AC Operating Conditions, on page 43

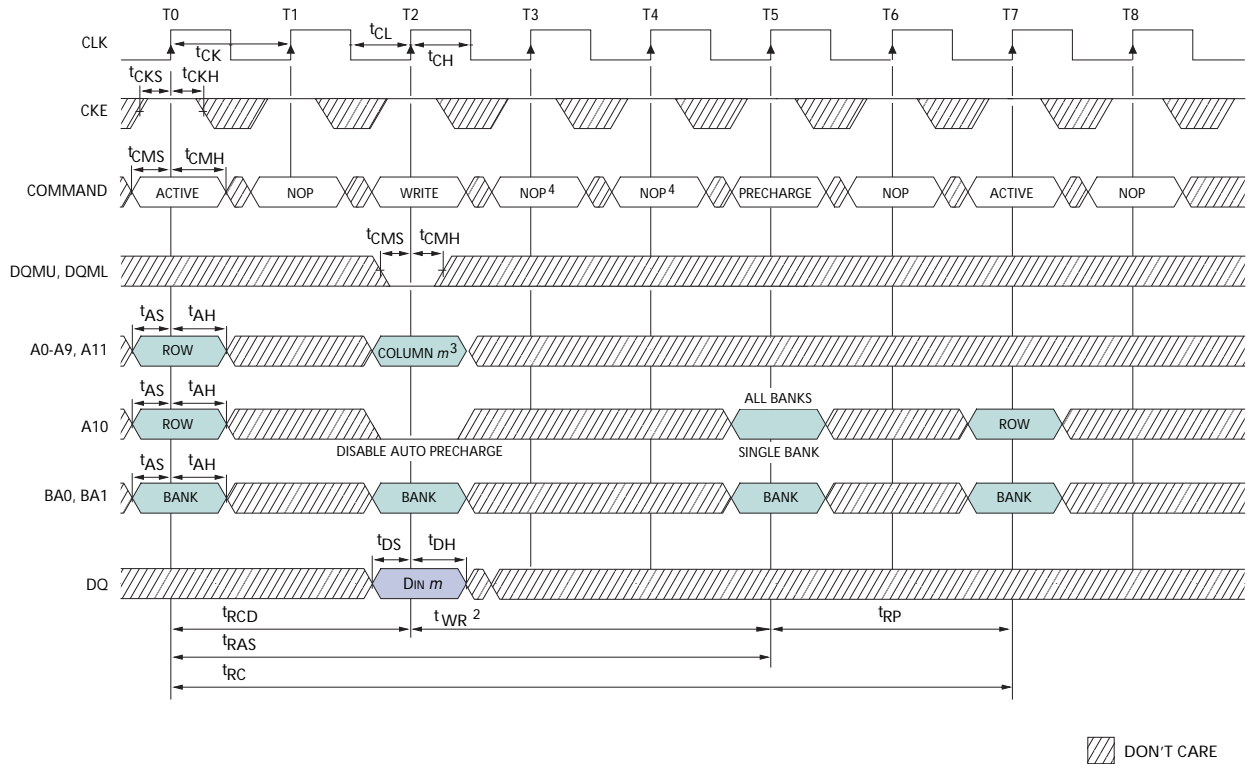
Figure 47: Write – Without Auto Precharge

NOTE:

1. For this example, the burst length = 4, and the WRITE burst is followed by a “manual” PRECHARGE.
2. 15ns is required between <DIN m + 3> and the PRECHARGE command, regardless of frequency.
3. x16: A9 and A11 = “Don’t Care”
x32: A8, A9, and A11 = “Don’t Care”
See Table 14, Electrical Characteristics and Recommended AC Operating Conditions, on page 43

Figure 48: Write – With Auto Precharge

NOTE:

1. For this example, the burst length = 4.
2. x16: A9 and A11 = "Don't Care"
 x32: A8, A9, and A11 = "Don't Care"
 See Table 14, Electrical Characteristics and Recommended AC Operating Conditions, on page 43

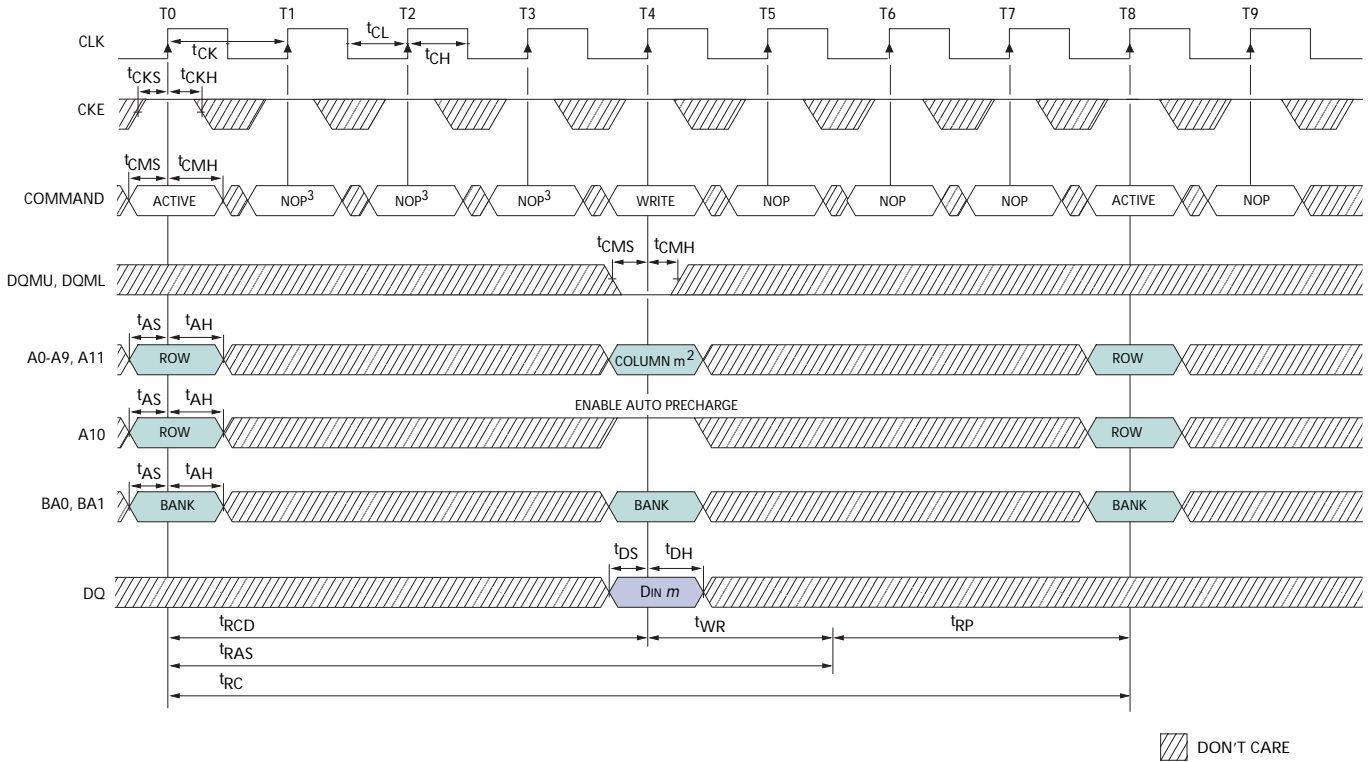
Figure 49: Single Write – Without Auto Precharge



DON'T CARE

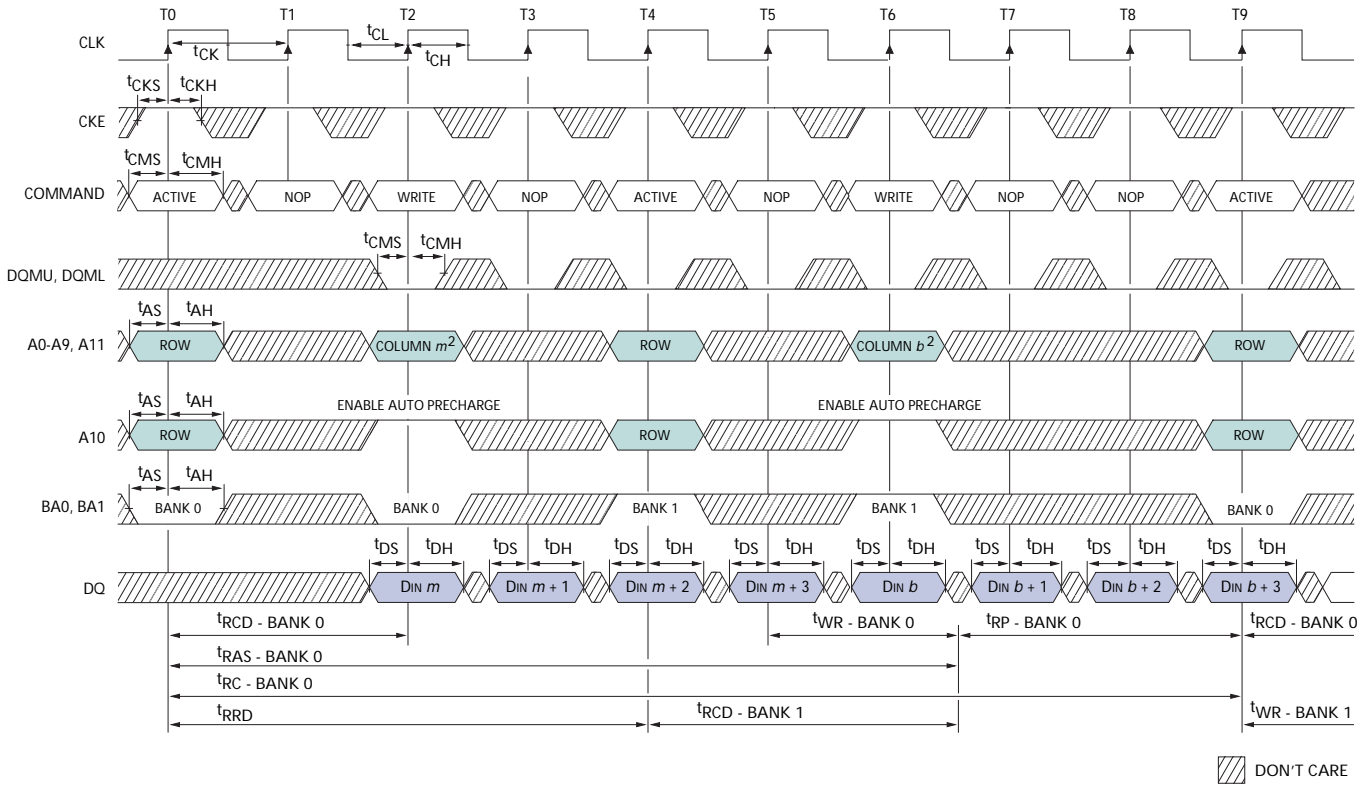
NOTE:

1. For this example, the burst length = 1, and the WRITE burst is followed by a “manual” PRECHARGE.
2. 15ns is required between <DIN m> and the PRECHARGE command, regardless of frequency.
3. x16:A9 and A11 = “Don’t Care”
x32:A8, A9, and A11 = “Don’t Care”
4. PRECHARGE command not allowed else t_{RAS} would be violated.
See Table 14, Electrical Characteristics and Recommended AC Operating Conditions, on page 43

Figure 50: Single Write – With Auto Precharge

NOTE:

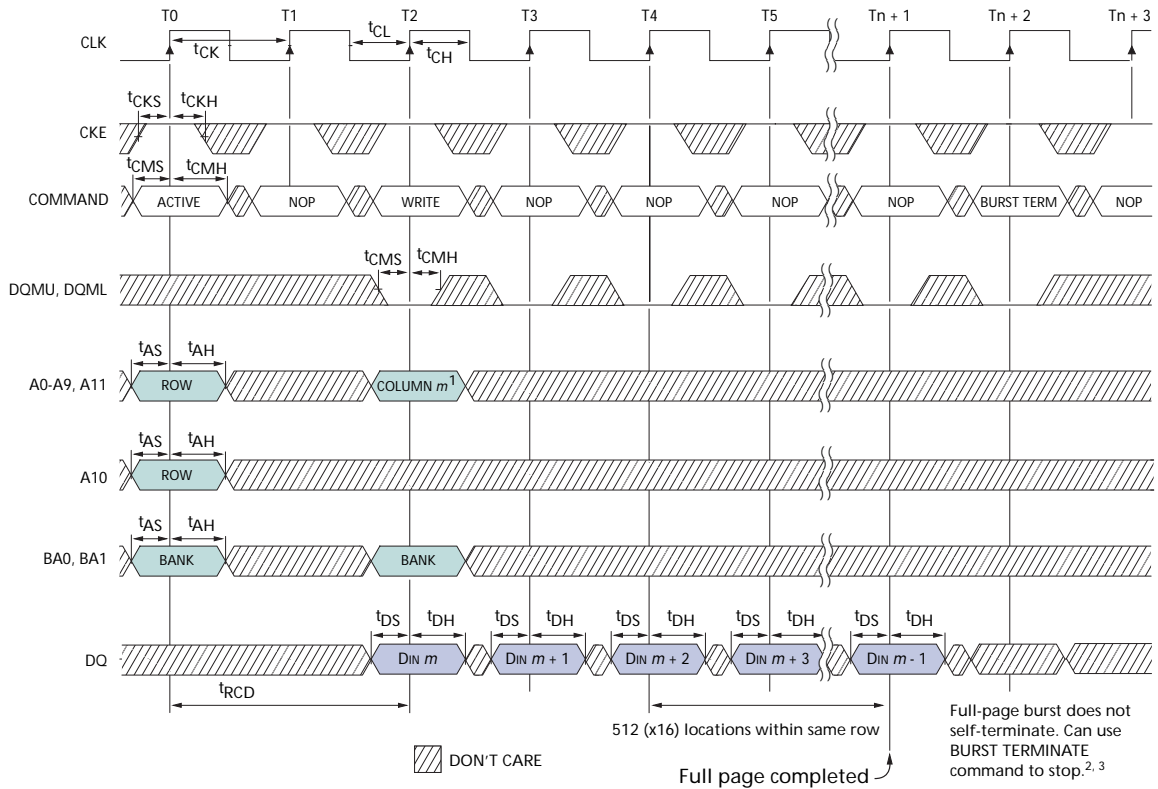
1. For this example, the burst length = 1, and the WRITE burst is followed by a “manual” PRECHARGE.
2. 15ns is required between <DIN m> and the PRECHARGE command, regardless of frequency.
3. x16:A9 and A11 = “Don’t Care”
x32:A8, A9, and A11 = “Don’t Care”
4. WRITE command not allowed else t_{RAS} would be violated.
See Table 14, Electrical Characteristics and Recommended AC Operating Conditions, on page 43

Figure 51: Alternating Bank Write Accesses



NOTE:

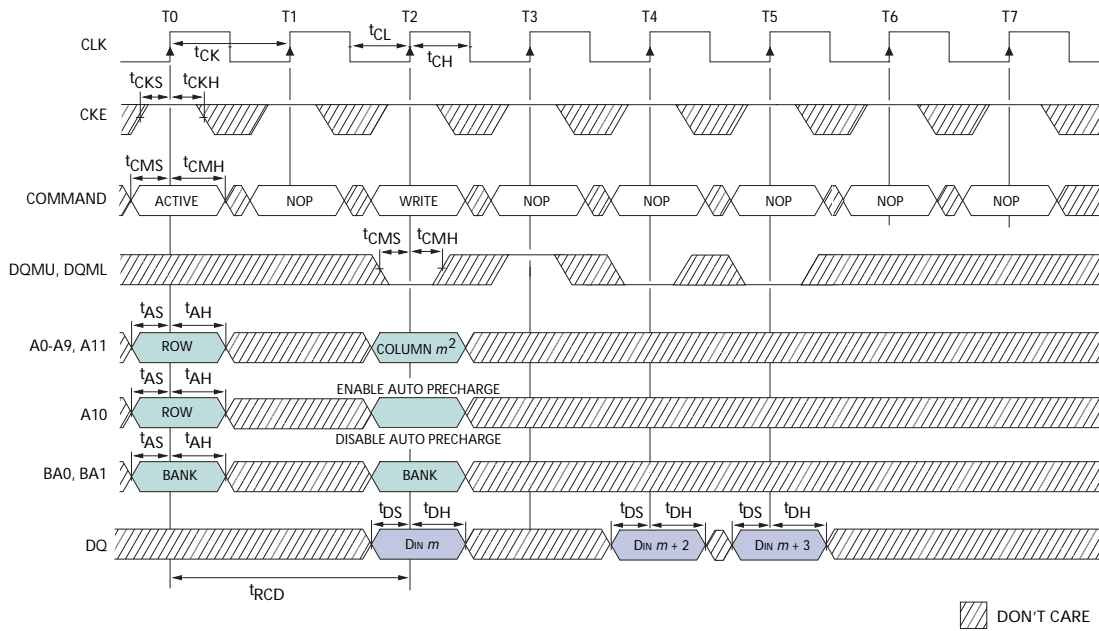
1. For this example, the burst length = 4.
 2. x16: A9 and A11 = "Don't Care"
 - x32: A8, A9, and A11 = "Don't Care"
- See Table 14, Electrical Characteristics and Recommended AC Operating Conditions, on page 43

Figure 52: Write – Full-page Burst

NOTE:

1. x16: A9 and A11 = "Don't Care"
x32: A8, A9, and A11 = "Don't Care"
2. t_{WR} must be satisfied prior to PRECHARGE command.
3. Page left open; no t_{RP} .

See Table 14, Electrical Characteristics and Recommended AC Operating Conditions, on page 43

Figure 53: Write – DQM Operation

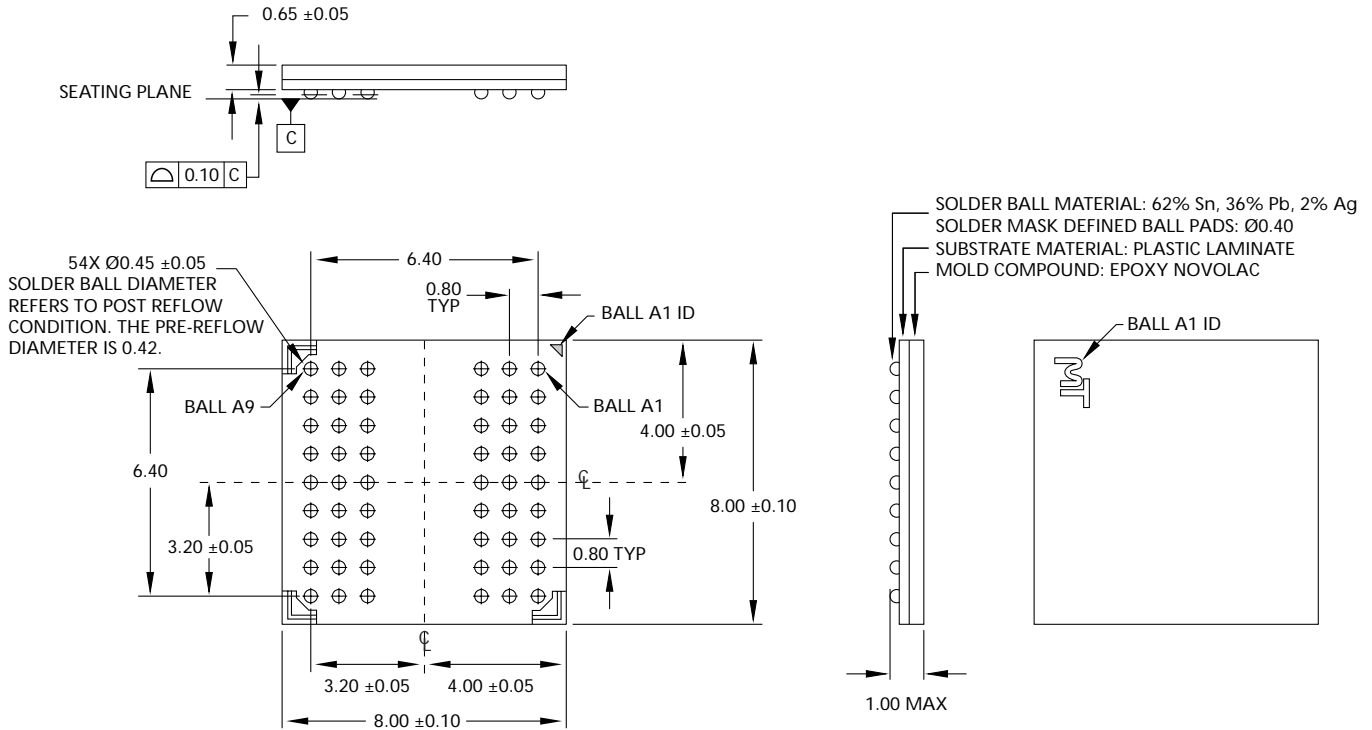


NOTE:

1. For this example, the burst length = 4.
2. x16: A9 and A11 = "Don't Care"
- x32: A8, A9, and A11 = "Don't Care."

See Table 14, Electrical Characteristics and Recommended AC Operating Conditions, on page 43

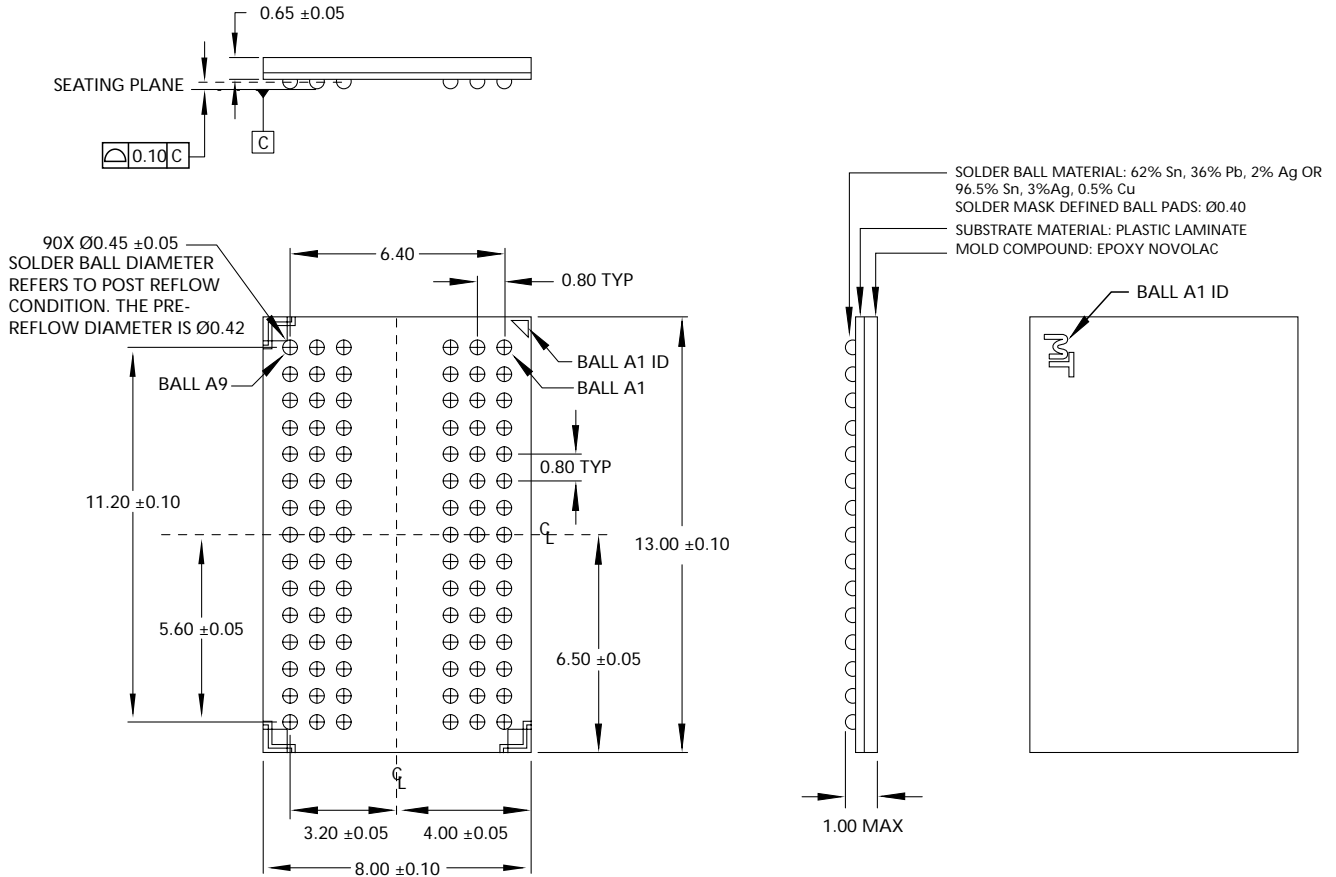
Figure 54: 54-Ball VFBGA (8mm x 8mm)



NOTE:

1. All dimensions in millimeters.

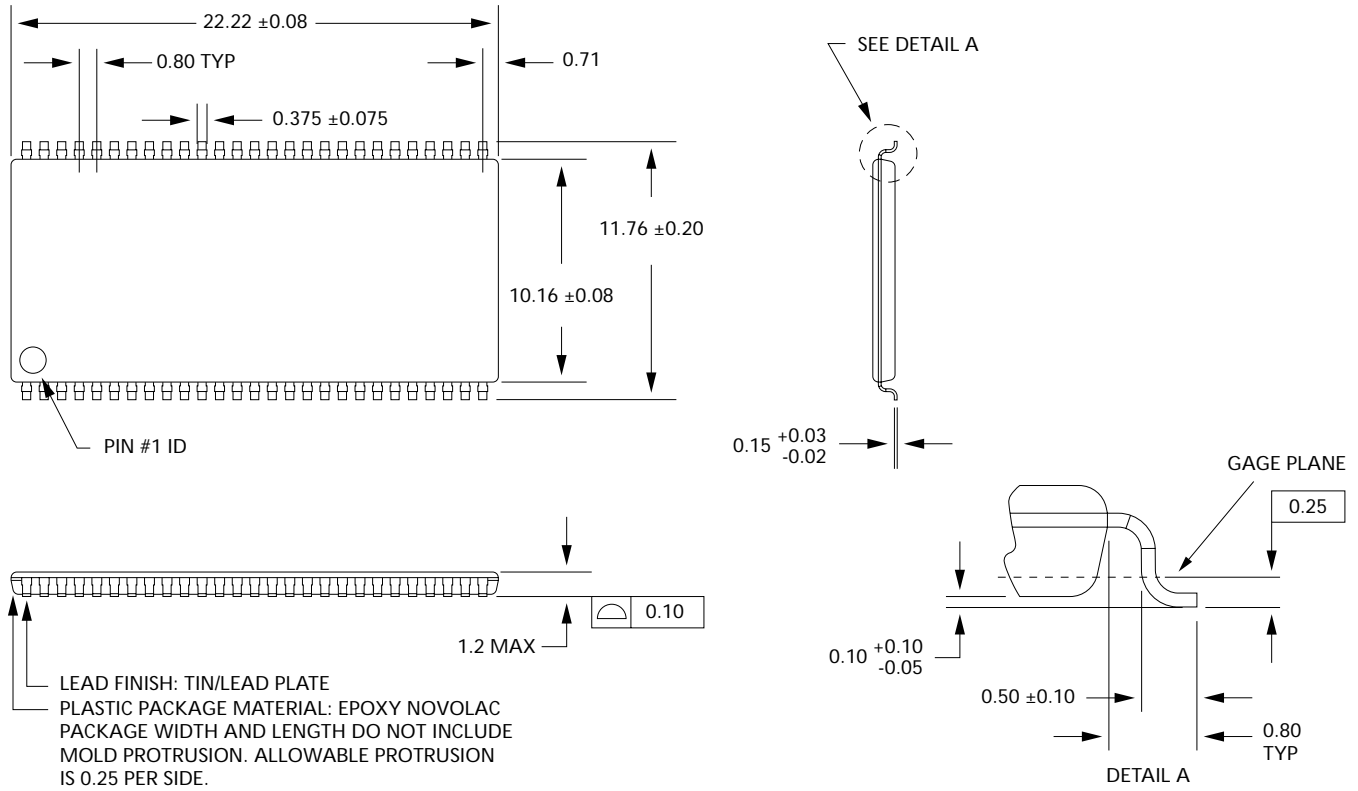
Figure 55: 90-Ball VFBGA (8mm x 13mm)



NOTE:

1. All dimensions in millimeters.
2. Recommended pad size for PCB is $0.4\text{mm} \pm 0.025\text{mm}$.

Figure 56: 54-Pin Plastic TSOP (400 mil)



NOTE:

1. All dimensions in millimeters.
2. Package width and length do not include mold protrusion; allowable mold protrusion is 0.25mm per side.



8000 S. Federal Way, P.O. Box 6, Boise, ID 83707-0006, Tel: 208-368-3900

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